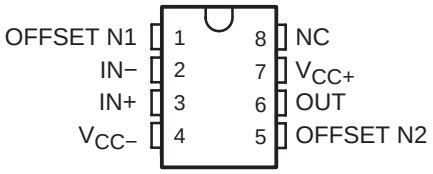
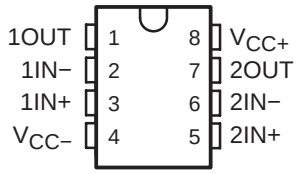
- **Very Low Power Consumption**
- **Typical Supply Current . . . 200 μA (Per Amplifier)**
- **Wide Common-Mode and Differential Voltage Ranges**
- **Low Input Bias and Offset Currents**
- **Common-Mode Input Voltage Range Includes V_{CC+}**
- **Output Short-Circuit Protection**
- **High Input Impedance . . . JFET-Input Stage**
- **Internal Frequency Compensation**
- **Latch-Up-Free Operation**
- **High Slew Rate . . . 3.5 V/μs Typ**

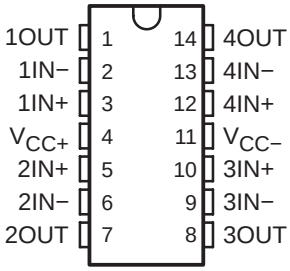
TL061, TL061A . . . D, P, OR PS PACKAGE
TL061B . . . P PACKAGE
(TOP VIEW)



TL062 . . . D, JG, P, PS, OR PW PACKAGE
TL062A . . . D, P, OR PS PACKAGE
TL062B . . . D OR P PACKAGE
(TOP VIEW)

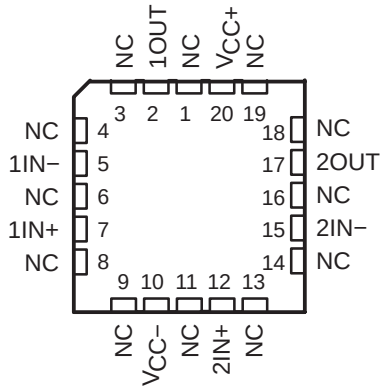


TL064 . . . D, J, N, NS, PW, OR W PACKAGE
TL064A, TL064B . . . D OR N PACKAGE
(TOP VIEW)

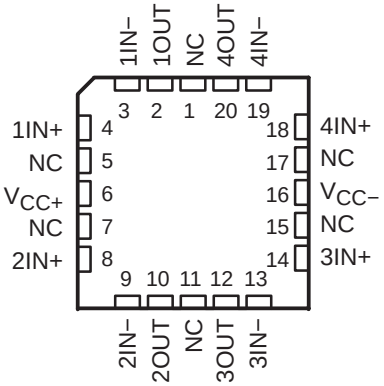


NC − No internal connection

TL062 . . . FK PACKAGE
(TOP VIEW)



TL064 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

The JFET-input operational amplifiers of the TL06_ series are designed as low-power versions of the TL08_ series amplifiers. They feature high input impedance, wide bandwidth, high slew rate, and low input offset and input bias currents. The TL06_ series features the same terminal assignments as the TL07_ and TL08_ series. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in an integrated circuit.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from −40°C to 85°C, and the M-suffix devices are characterized for operation over the full military temperature range of −55°C to 125°C.

description/ordering information (continued)

ORDERING INFORMATION

T_A	V_{IO}MAX AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	15 mV	PDIP (P)	Tube of 50	TL061CP	TL061CP
				TL062CP	TL062CP
		PDIP (N)	Tube of 25	TL064CN	TL064CN
		SOIC (D)	Tube of 75	TL061CD	TL061C
			Reel of 2500	TL061CDR	
			Tube of 75	TL062CD	TL062C
			Reel of 2500	TL062CDR	
			Tube of 50	TL064CD	TL064C
			Reel of 2500	TL064CDR	
		SOP (PS)	Reel of 2000	TL061CPSR	T061
				TL062CPSR	T062
		SOP (NS)	Reel of 2000	TL064CNSR	TL064
		TSSOP (PW)	Tube of 150	TL062CPW	T062
			Reel of 2000	TL062CPWR	
			Tube of 90	TL064CPW	T064
			Reel of 2000	TL064CPWR	
	6 mV	PDIP (P)	Tube of 50	TL061ACP	TL061ACP
				TL062ACP	TL062ACP
		PDIP (N)	Tube of 25	TL064ACN	TL064ACN
		SOIC (D)	Tube of 75	TL061ACD	061AC
			Reel of 2500	TL061ACDR	
			Tube of 75	TL062ACD	062AC
			Reel of 2500	TL062ACDR	
			Tube of 50	TL064ACD	TL064AC
			Reel of 2500	TL064ACDR	
		SOP (PS)	Reel of 2000	TL061ACPSR	T061A
				TL062ACPSR	T062A
	3 mV	PDIP (P)	Tube of 50	TL061BCP	TL061BCP
				TL062BCP	TL062BCP
		PDIP (N)	Tube of 25	TL064BCN	TL064BCN
		SOIC (D)	Tube of 75	TL062BCD	062BC
			Reel of 2500	TL062BCDR	
			Tube of 50	TL064BCD	TL064BC
			Reel of 2500	TL064BCDR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

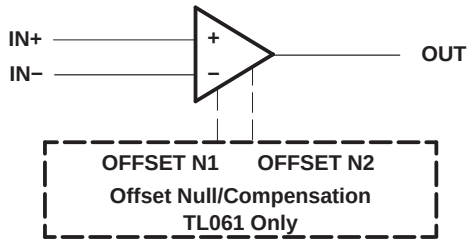
description/ordering information (continued)

ORDERING INFORMATION (continued)

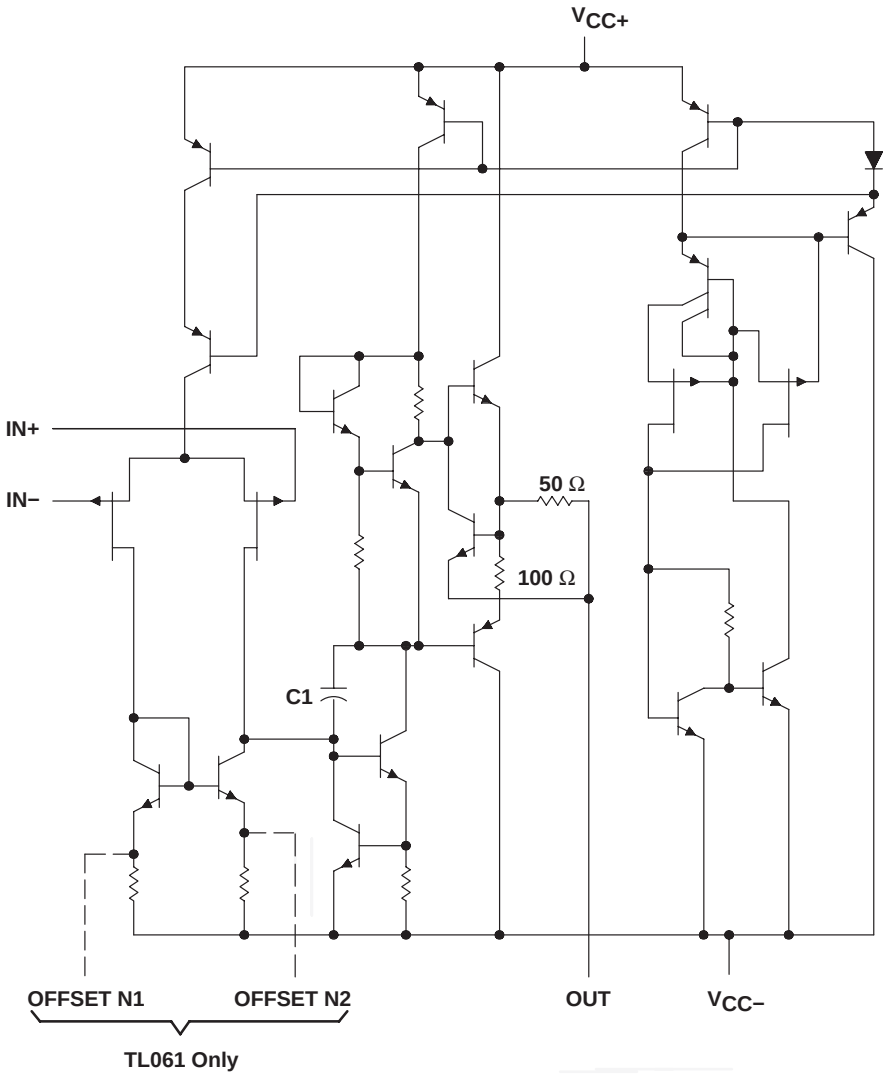
T_A	V_{IO}MAX AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	6 mV	PDIP (P)	Tube of 50	TL061IP	TL061IP
				TL062IP	TL062IP
		PDIP (N)	Tube of 25	TL064IN	TL064IN
		SOIC (D)	Tube of 75	TL061ID	TL061I
			Reel of 2000	TL061IDR	
			Tube of 75	TL062ID	TL062I
			Reel of 2000	TL062IDR	
			Tube of 50	TL064ID	TL064I
			Reel of 2500	TL064IDR	
		TSSOP (PW)	Reel of 2000	TL062IPWR	TL062I
−55°C to 125°C	6 mV	CDIP (JG)	Tube of 50	TL062MJG	TL062MJG
		LCCC (FK)	Tube of 55	TL062MFK	TL062MFK
	9 mV	CDIP (J)	Tube of 25	TL064MJ	TL064MJ
		CFP (W)	Tube of 150	TL064MW	TL064MW
		LCCC (FK)	Tube of 55	TL064MFK	TL064MFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each amplifier)



schematic (each amplifier)



C1 = 10 pF on TL061, TL062, and TL064
Component values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

		TL06_C TL06_AC TL06_BC	TL06_I	TL06_M	UNIT
Supply voltage, V_{CC+} (see Note 1)		18	18	18	V
Supply voltage, V_{CC-} (see Note 1)		−18	−18	−18	V
Differential input voltage, V_{ID} (see Note 2)		±30	±30	±30	V
Input voltage, V_I (see Notes 1 and 3)		±15	±15	±15	V
Duration of output short circuit (see Note 4)		Unlimited	Unlimited	Unlimited	
Package thermal impedance, θ_{JA} (see Notes 5 and 6)	D (8-pin) package	97	97		°C/W
	D (14-pin) package	86	86		
	N package	80	80		
	NS package	76	76		
	P package	85	85		
	PS package	95	95		
	PW (8-pin) package	149	149		
	PW (14-pin) package	113	113		
Package thermal impedance, θ_{JC} (see Notes 7 and 8)	FK package			5.61	°C/W
	J package			15.05	
	JG package			14.5	
	W package			14.65	
Operating virtual junction temperature, T_J		150	150	150	°C
Case temperature for 60 seconds	FK package			260	°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	J, JG, U, or W package			300	°C
Lead temperature 1,6 mm (1/6 inch) from case for 10 seconds	D, N, NS, P, PS, or PW package	260	260		°C
Storage temperature range, T_{stg}		−65 to 150	−65 to 150	−65 to 150	°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:
1. All voltage values except differential voltages are with respect to the midpoint between V_{CC+} and V_{CC-}.
2. Differential voltages are at IN+ with respect to IN−.
3. The magnitude of the input voltage should never exceed the magnitude of the supply voltage or 15 V, whichever is less.
4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
6. The package thermal impedance is calculated in accordance with JESD 51-7.
7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC}, and T_C. The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
8. The package thermal impedance is calculated in accordance with MIL-STD-883.

electrical characteristics, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TL061C TL062C TL064C			TL061AC TL062AC TL064AC			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0, R_S = 50 Ω	T_A = 25°C		3	15		3	6	mV
			T_A = Full range			20			7.5	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	V_O = 0, R_S = 50 Ω, T_A = Full range			10			10		µV/°C
I_{IO}	Input offset current	V_O = 0	T_A = 25°C		5	200		5	100	pA
			T_A = Full range			5			3	nA
I_{IB}	Input bias current‡	V_O = 0	T_A = 25°C		30	400		30	200	pA
			T_A = Full range			10			7	nA
V_{ICR}	Common-mode input voltage range	T_A = 25°C		±11	−12 to 15		±11	−12 to 15		V
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ,	T_A = 25°C	±10	±13.5		±10	±13.5		V
		R_L ≥ 10 kΩ,	T_A = Full range	±10			±10			
A_{VD}	Large-signal differential voltage amplification	V_O = ± 10 V, R_L ≥ 10 kΩ	T_A = 25°C	3	6		4	6		V/mV
			T_A = Full range	3			4			
B_1	Unity-gain bandwidth	R_L = 10 kΩ,	T_A = 25°C		1			1		MHz
r_i	Input resistance	T_A = 25°C			10^{12}			10^{12}		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min, V_O = 0, R_S = 50 Ω, T_A = 25°C		70	86		80	86		dB
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	V_{CC} = ± 9 V to ± 15 V, V_O = 0, R_S = 50 Ω, T_A = 25°C		70	95		80	95		dB
P_D	Total power dissipation (each amplifier)	V_O = 0, No load	T_A = 25°C,		6	7.5		6	7.5	mW
I_{CC}	Supply current (each amplifier)	V_O = 0, No load	T_A = 25°C,		200	250		200	250	µA
V_{O1}/V_{O2}	Crosstalk attenuation	A_{VD} = 100,	T_A = 25°C		120			120		dB

† All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified. Full range for T_A is 0°C to 70°C for TL06_C, TL06_AC, and TL06_BC and −40°C to 85°C for TL06_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

electrical characteristics, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TL061BC TL062BC TL064BC			TL061I TL062I TL064I			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0, R_S = 50 Ω	T_A = 25°C		2	3		3	6	mV
			T_A = Full range			5			9	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	V_O = 0, R_S = 50 Ω, T_A = Full range			10			10		µV/°C
I_{IO}	Input offset current	V_O = 0	T_A = 25°C		5	100		5	100	pA
			T_A = Full range			3			10	nA
I_{IB}	Input bias current‡	V_O = 0	T_A = 25°C		30	200		30	200	pA
			T_A = Full range			7			20	nA
V_{ICR}	Common-mode input voltage range	T_A = 25°C		±11	−12 to 15		±11	−12 to 15		V
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ,	T_A = 25°C	±10	±13.5		±10	±13.5		V
		R_L ≥ 10 kΩ,	T_A = Full range	±10			±10			
A_{VD}	Large-signal differential voltage amplification	V_O = ± 10 V, R_L ≥ 10 kΩ	T_A = 25°C	4	6		4	6		V/mV
			T_A = Full range	4			4			
B_1	Unity-gain bandwidth	R_L = 10 kΩ,	T_A = 25°C		1			1		MHz
r_i	Input resistance	T_A = 25°C			10^{12}			10^{12}		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min, V_O = 0, R_S = 50 Ω, T_A = 25°C		80	86		80	86		dB
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	V_{CC} = ± 9 V to ± 15 V, V_O = 0, R_S = 50 Ω, T_A = 25°C		80	95		80	95		dB
P_D	Total power dissipation (each amplifier)	V_O = 0, No load	T_A = 25°C,		6	7.5		6	7.5	mW
I_{CC}	Supply current (each amplifier)	V_O = 0, No load	T_A = 25°C,		200	250		200	250	µA
V_{O1}/V_{O2}	Crosstalk attenuation	A_{VD} = 100,	T_A = 25°C		120			120		dB

† All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T_A is 0°C to 70°C for TL06_C, TL06_AC, and TL06_BC and −40°C to 85°C for TL06_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

electrical characteristics, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TL061M TL062M			TL064M			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0, R_S = 50 Ω	T_A = 25°C		3	6		3	9	mV
			T_A = −55°C to 125°C			9			15	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	V_O = 0, R_S = 50 Ω, T_A = −55°C to 125°C			10			10		µV/°C
I_{IO}	Input offset current	V_O = 0	T_A = 25°C		5	100		5	100	pA
			T_A = −55°C			20*			20*	nA
			T_A = 125°C			20			20	
I_{IB}	Input bias current‡	V_O = 0	T_A = 25°C		30	200		30	200	pA
			T_A = −55°C			50*			50*	nA
			T_A = 125°C			50			50	
V_{ICR}	Common-mode input voltage range	T_A = 25°C		±11.5	−12 to 15		±11.5	−12 to 15		V
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ,	T_A = 25°C	±10	±13.5		±10	±13.5		V
		R_L ≥ 10 kΩ,	T_A = −55°C to 125°C	±10			±10			
A_{VD}	Large-signal differential voltage amplification	V_O = ±10 V, R_L ≥ 10 kΩ	T_A = 25°C	4	6		4	6		V/mV
			T_A = −55°C to 125°C	4			4			
B_1	Unity-gain bandwidth	R_L = 10 kΩ,	T_A = 25°C							MHz
r_i	Input resistance	T_A = 25°C			10^{12}			10^{12}		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min, V_O = 0, R_S = 50 Ω, T_A = 25°C		80	86		80	86		dB
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	V_{CC} = ±9 V to ±15 V, V_O = 0, R_S = 50 Ω, T_A = 25°C		80	95		80	95		dB
P_D	Total power dissipation (each amplifier)	V_O = 0, No load	T_A = 25°C,		6	7.5		6	7.5	mW
I_{CC}	Supply current (each amplifier)	V_O = 0, No load	T_A = 25°C,		200	250		200	250	µA
V_{O1}/V_{O2}	Crosstalk attenuation	A_{VD} = 100,	T_A = 25°C		120			120		dB

* This parameter is not production tested.
† All characteristics are measured under open-loop conditions, with zero common-mode voltage, unless otherwise specified.
‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain (see Note 5)	V_I = 10 V, R_L = 10 kΩ,	C_L = 100 pF, See Figure 1	1.5	3.5		V/µs
t_r	Rise time	V_I = 20 mV, C_L = 100 pF,	R_L = 10 kΩ, See Figure 1		0.2		µs
	Overshoot factor				10%		
V_n	Equivalent input noise voltage	R_S = 20 Ω,	f = 1 kHz		42		nV/√Hz

NOTE 5: Slew rate at −55°C to 125°C is 0.7 V/µs min.

PARAMETER MEASUREMENT INFORMATION

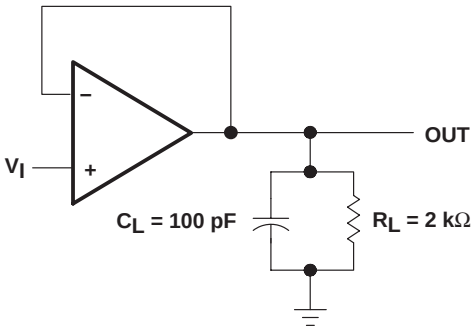


Figure 1. Unity-Gain Amplifier

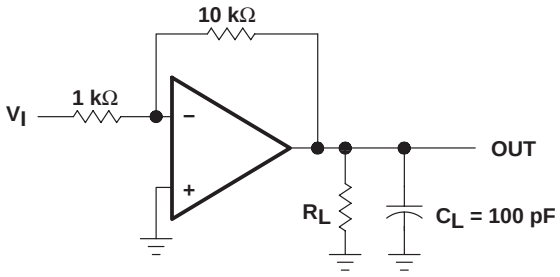


Figure 2. Gain-of-10 Inverting Amplifier

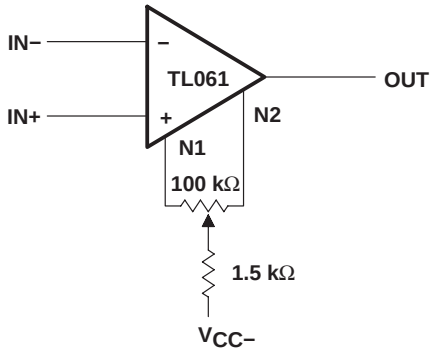


Figure 3. Input Offset-Voltage Null Circuit

TYPICAL CHARACTERISTICS

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TYPICAL CHARACTERISTICS†

MAXIMUM PEAK OUTPUT VOLTAGE vs SUPPLY VOLTAGE

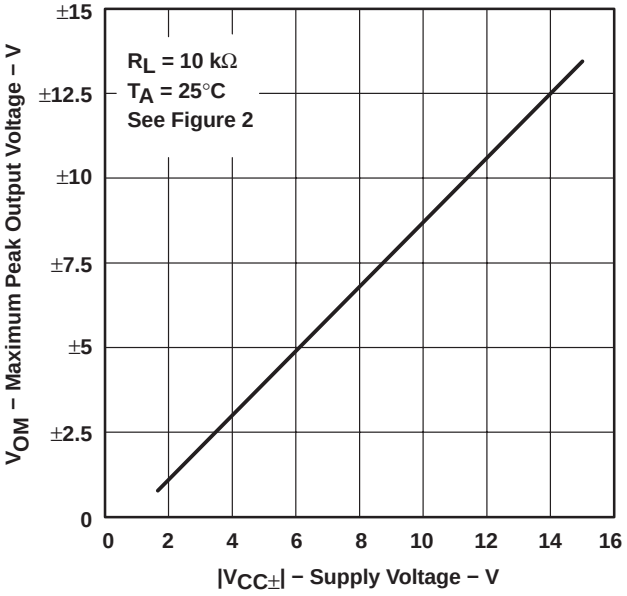

Figure 4

MAXIMUM PEAK OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

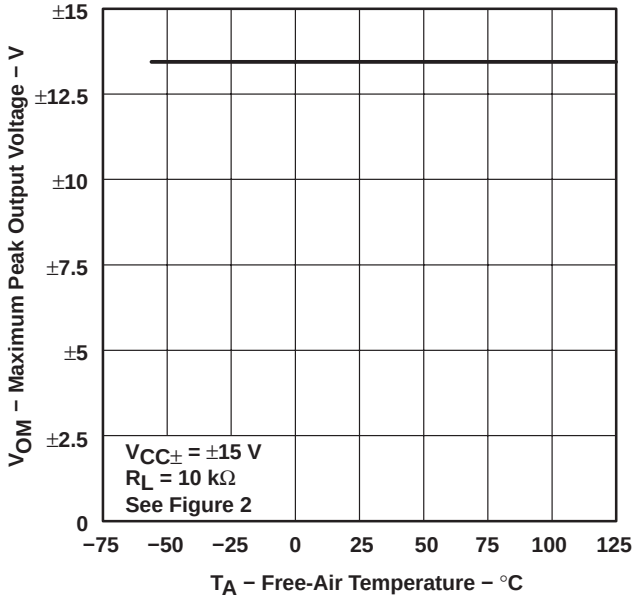

Figure 5

MAXIMUM PEAK OUTPUT VOLTAGE vs LOAD RESISTANCE

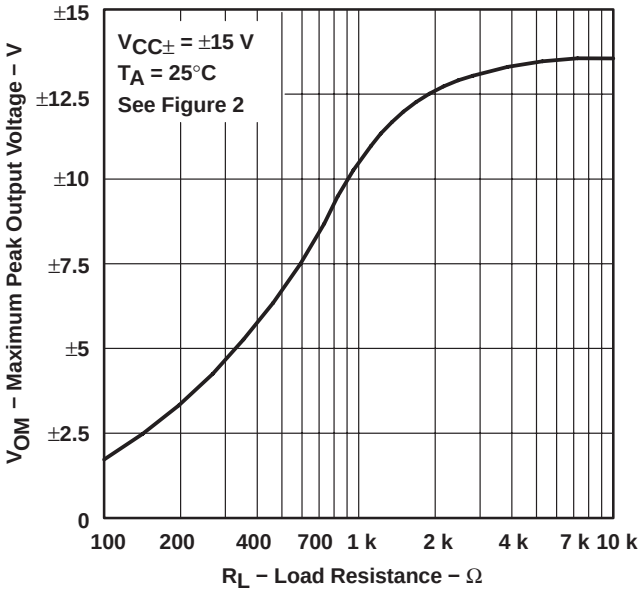

Figure 6

MAXIMUM PEAK OUTPUT VOLTAGE vs FREQUENCY

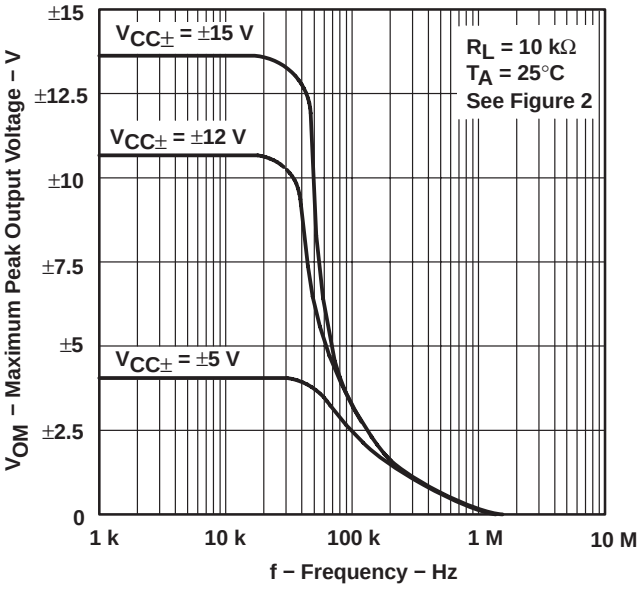

Figure 7

† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREE-AIR TEMPERATURE

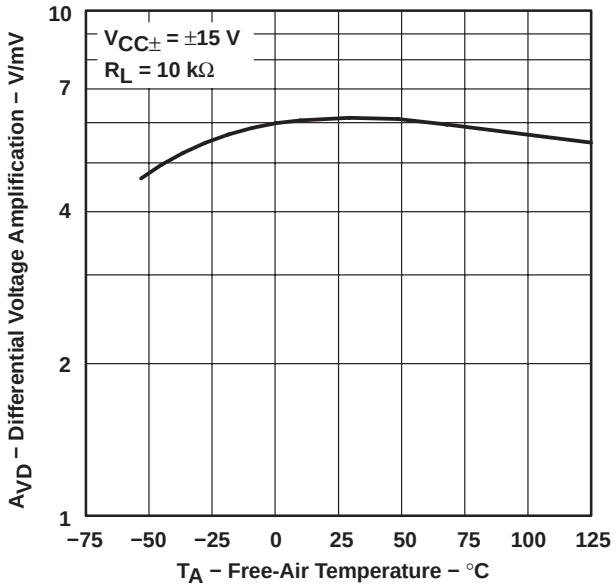

Figure 8

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT vs FREQUENCY

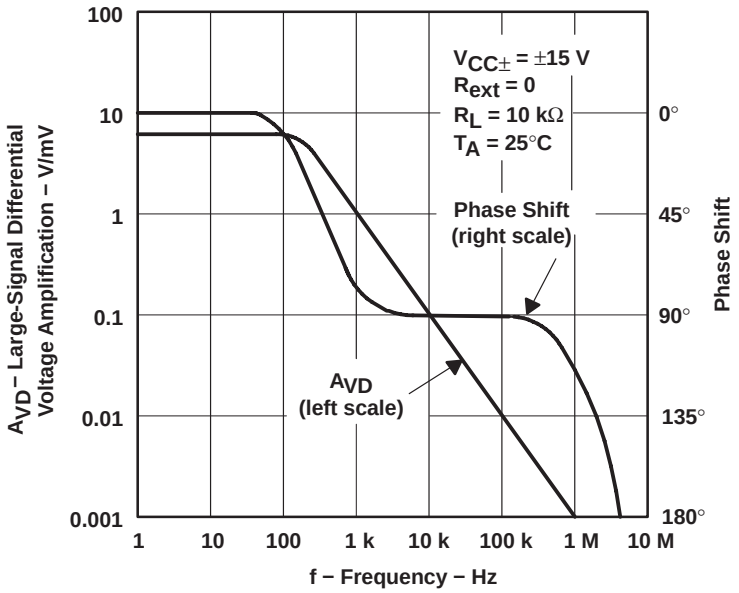

Figure 9

† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

SUPPLY CURRENT vs SUPPLY VOLTAGE

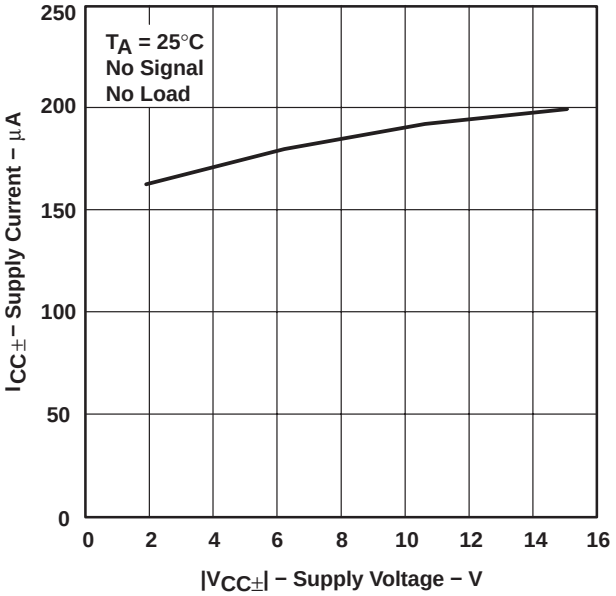

Figure 10

SUPPLY CURRENT vs FREE-AIR TEMPERATURE

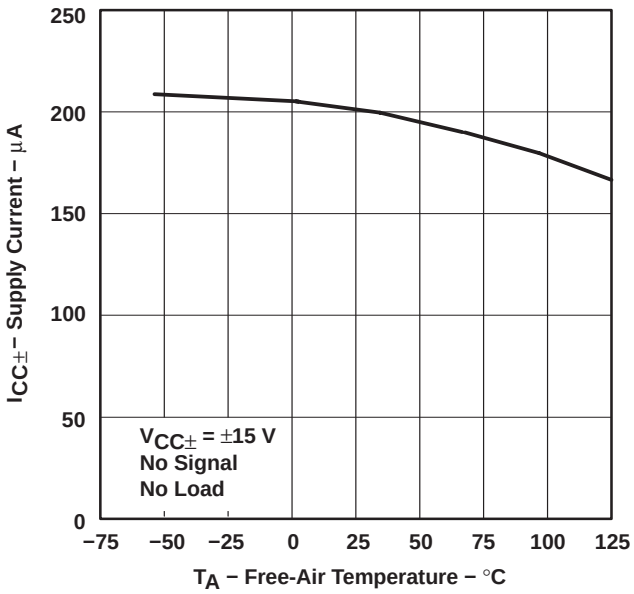

Figure 11

TOTAL POWER DISSIPATION vs FREE-AIR TEMPERATURE

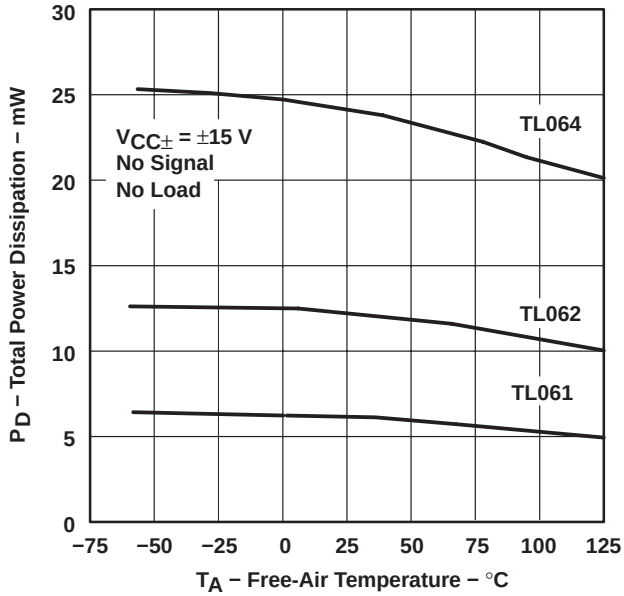

Figure 12

ALL EXCEPT TL06_C COMMON-MODE REJECTION RATIO vs FREE-AIR TEMPERATURE

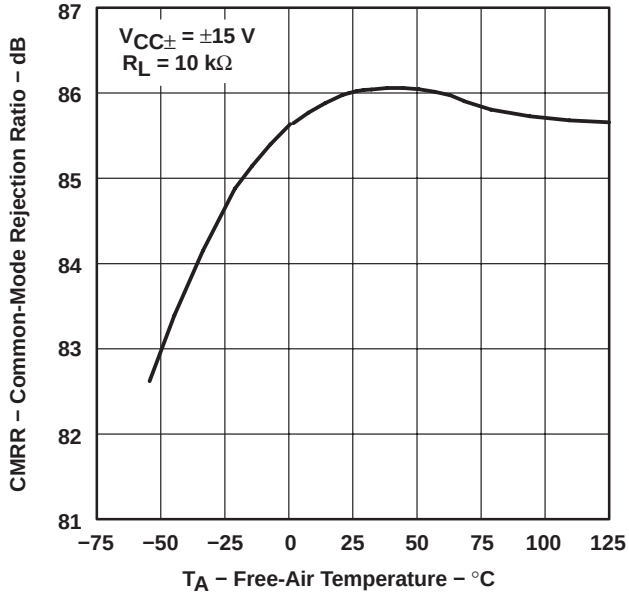

Figure 13

† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

NORMALIZED UNITY-GAIN BANDWIDTH, SLEW RATE, AND PHASE SHIFT vs FREE-AIR TEMPERATURE

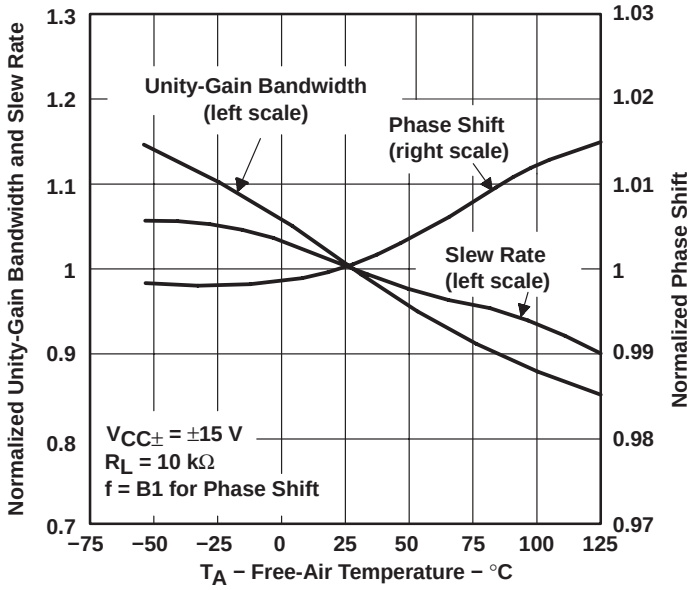

Figure 14

INPUT BIAS CURRENT vs FREE-AIR TEMPERATURE

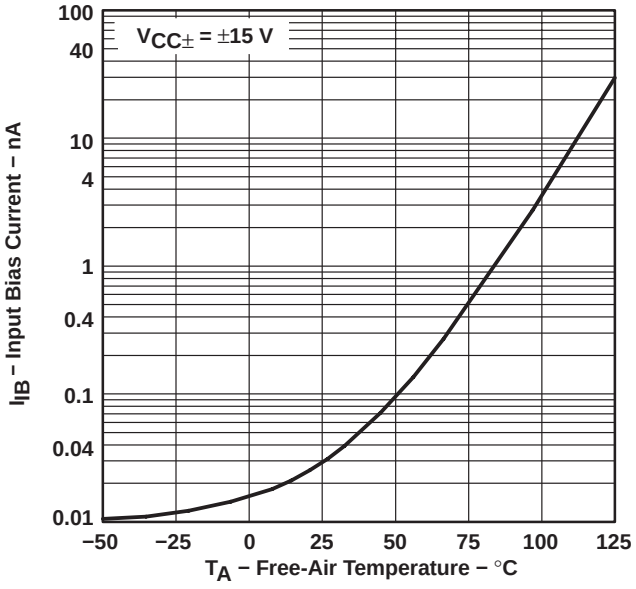

Figure 15

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE vs TIME

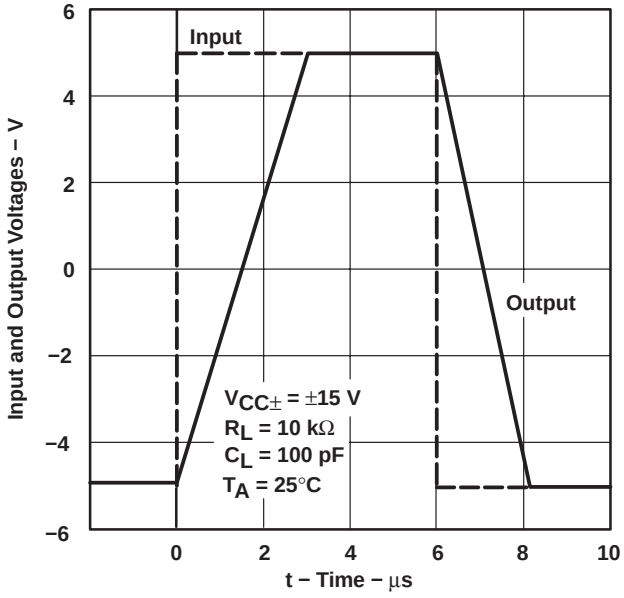

Figure 16

TYPICAL CHARACTERISTICS

OUTPUT VOLTAGE vs ELAPSED TIME

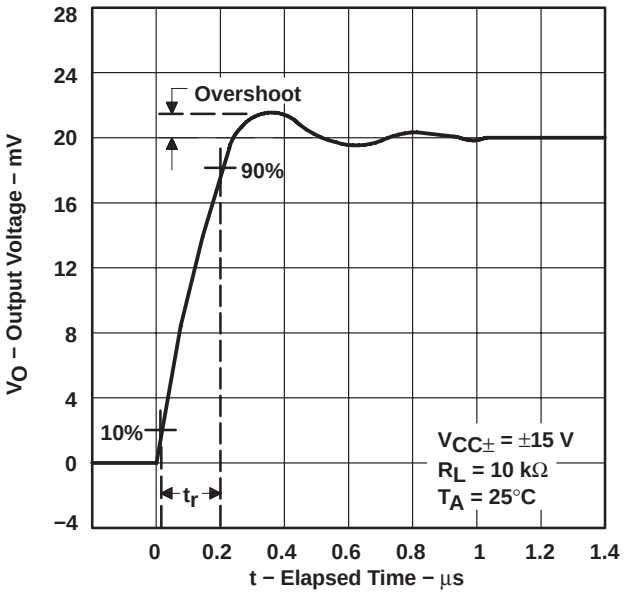

Figure 17

EQUIVALENT INPUT NOISE VOLTAGE vs FREQUENCY

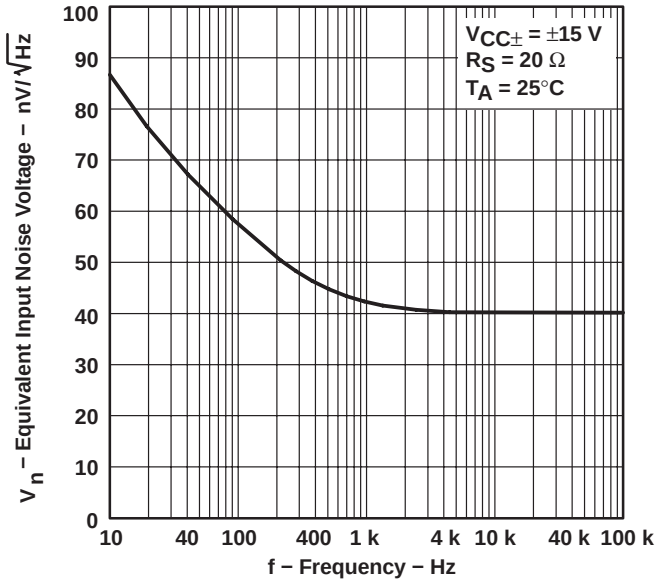

Figure 18

APPLICATION INFORMATION

Table of Application Diagrams

APPLICATION DIAGRAM	PART NUMBER	FIGURE
Instrumentation amplifier	TL064	19
0.5-Hz square-wave oscillator	TL061	20
High-Q notch filter	TL061	21
Audio-distribution amplifier	TL064	22
Low-level light detector preamplifier	TL061	23
AC amplifier	TL061	24
Microphone preamplifier with tone control	TL061	25
Instrumentation amplifier	TL062	26
IC preamplifier	TL062	27

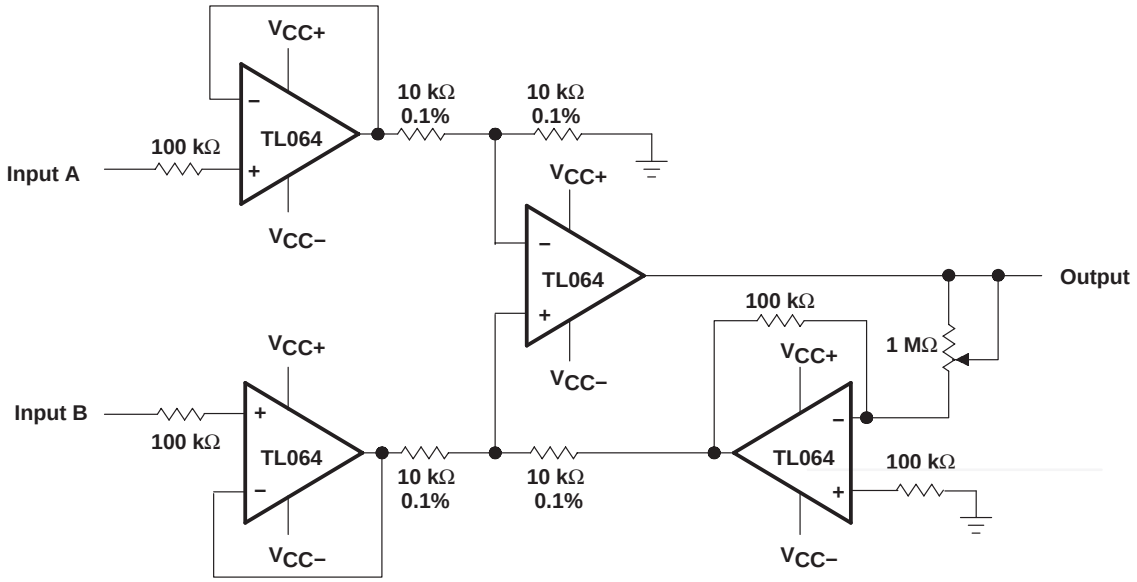

Figure 19. Instrumentation Amplifier

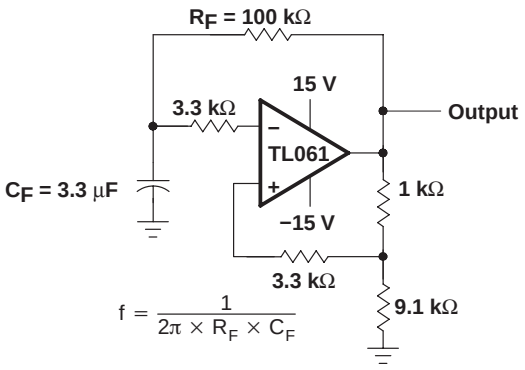

Figure 20. 0.5-Hz Square-Wave Oscillator

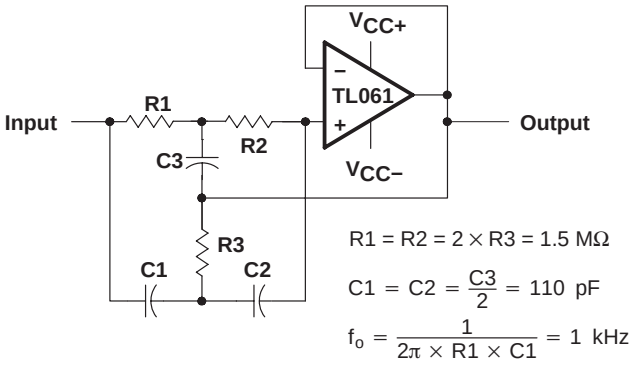

Figure 21. High-Q Notch Filter

APPLICATION INFORMATION

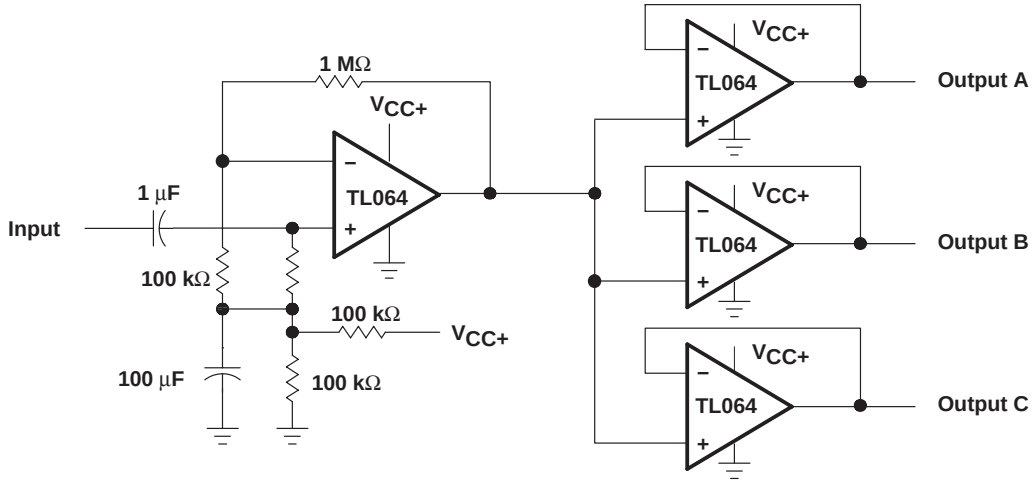

Figure 22. Audio-Distribution Amplifier

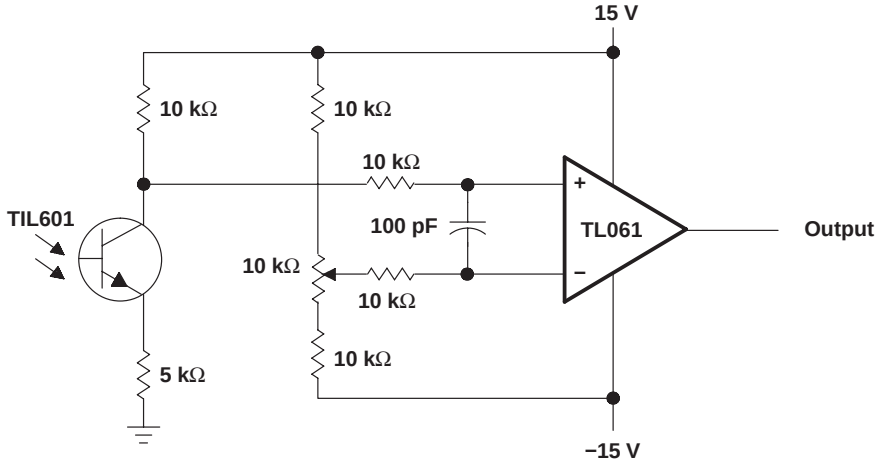

Figure 23. Low-Level Light Detector Preamplifier

APPLICATION INFORMATION

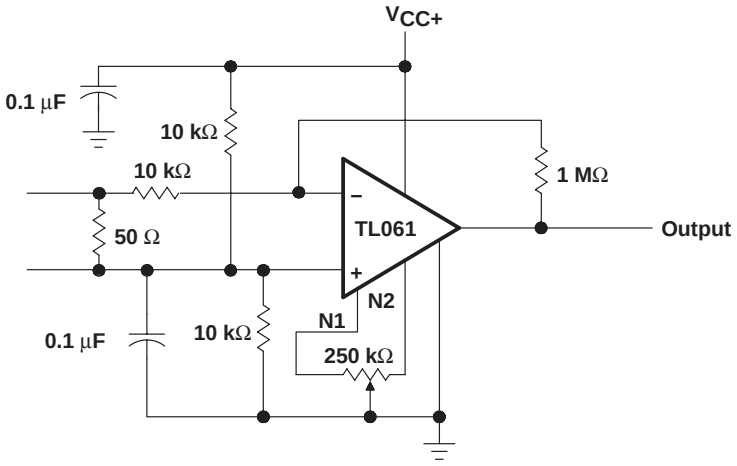

Figure 24. AC Amplifier

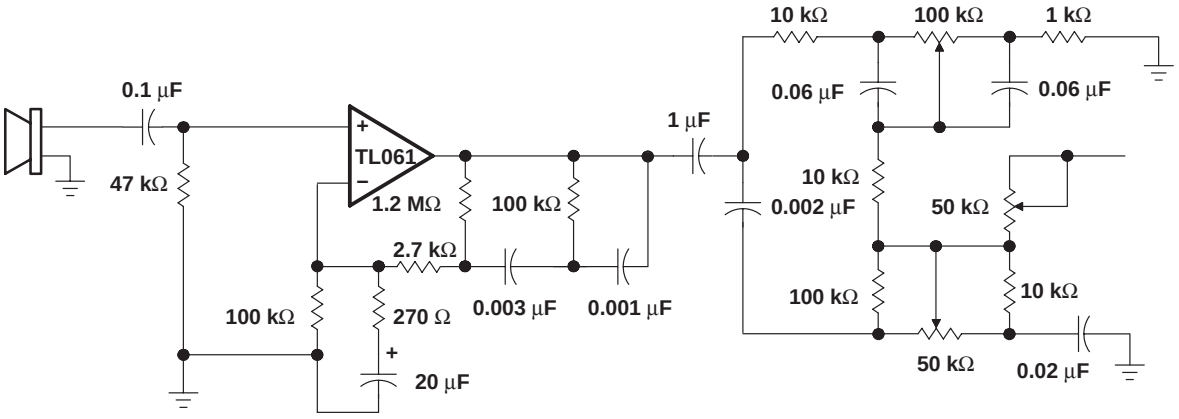

Figure 25. Microphone Preamplifier With Tone Control

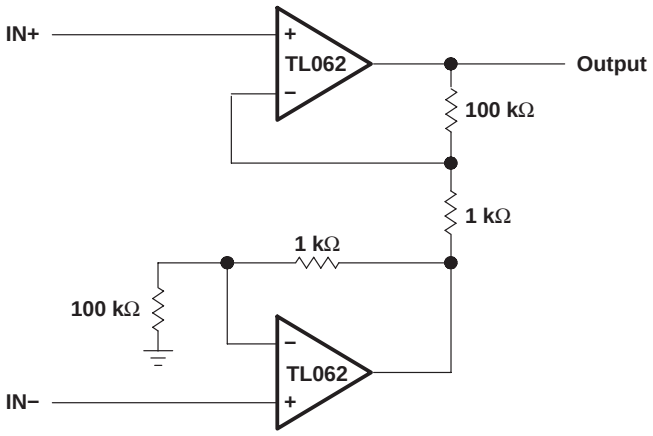

Figure 26. Instrumentation Amplifier

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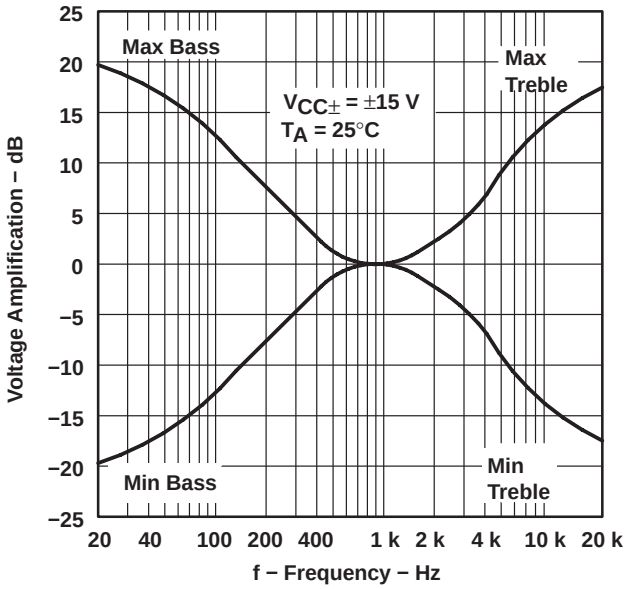
APPLICATION INFORMATION

IC PREAMPLIFIER RESPONSE CHARACTERISTICS



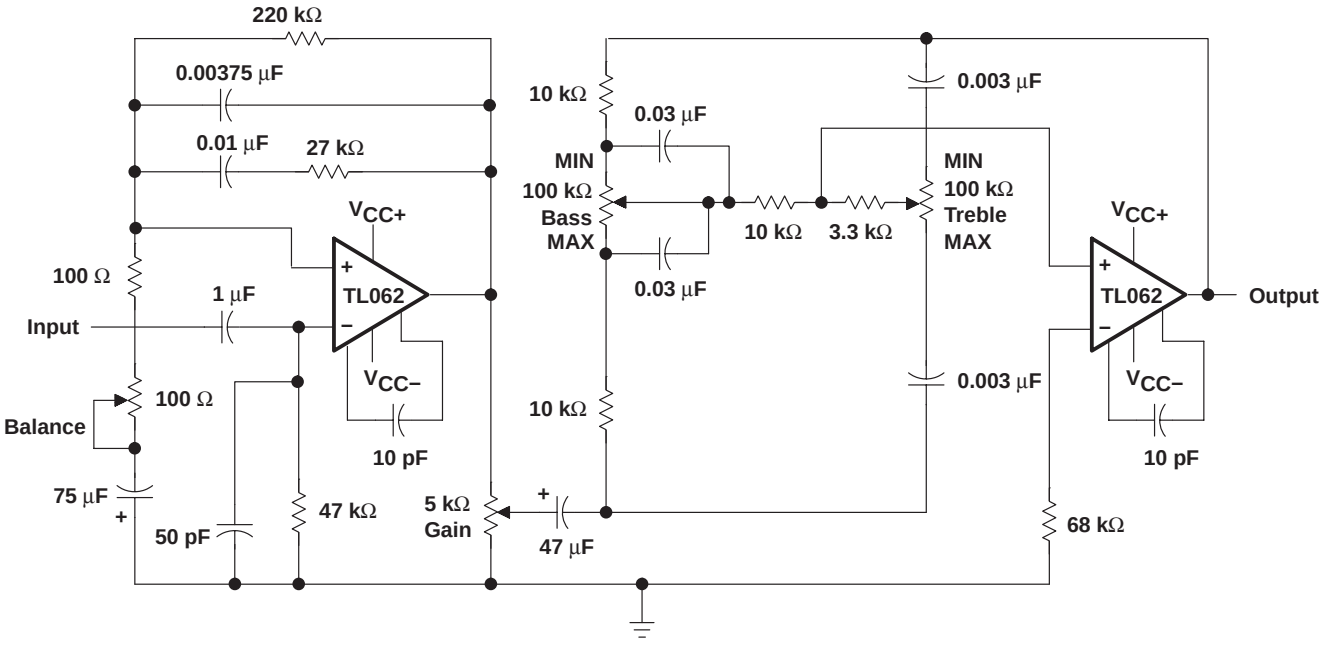


Figure 27. IC Preamplifier

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
81023012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
81023022A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8102302HA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	
8102302PA	ACTIVE	CDIP	JG	8	1	TBD	Call TI	Call TI	
81023032A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8102303CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
8102303DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
TL061ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061BCD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	
TL061BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL061CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	
TL061ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL061IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL061MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	
TL061MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	
TL062ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL062ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	
TL062ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL062CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	
TL062CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062CPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	
TL062CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	
TL062CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL062IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	
TL062IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL062IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL062MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
TL062MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
TL062MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
TL064ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL064BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064BCDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064BCDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL064CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	
TL064CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL064INS	ACTIVE	SO	NS	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064INSG4	ACTIVE	SO	NS	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064INSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064INSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL064MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
TL064MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL064MJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
TL064MJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
TL064MWB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

OTHER QUALIFIED VERSIONS OF TL062, TL062M, TL064, TL064M :

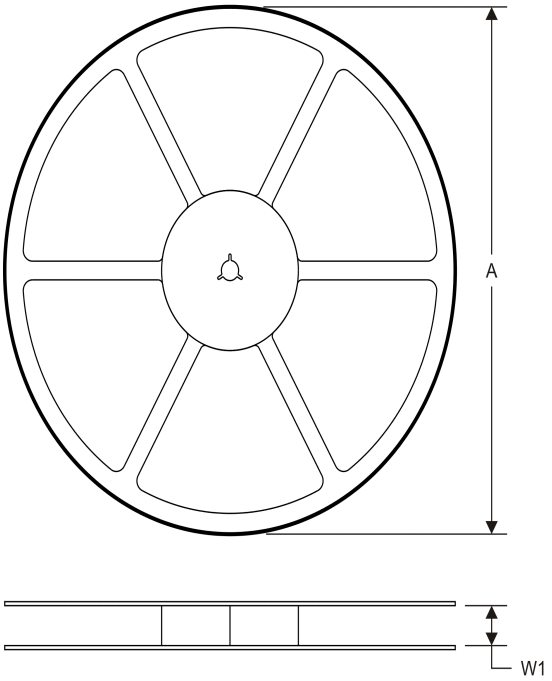
- Catalog: TL062, TL064
- Military: TL062M, TL064M

NOTE: Qualified Version Definitions:

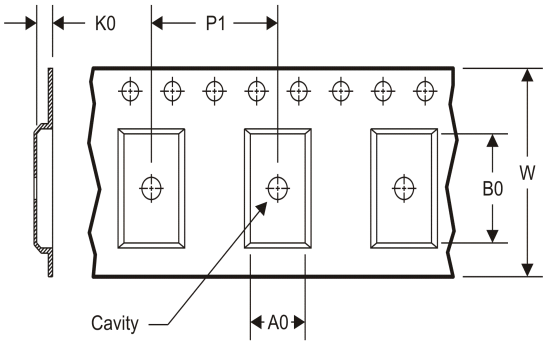
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

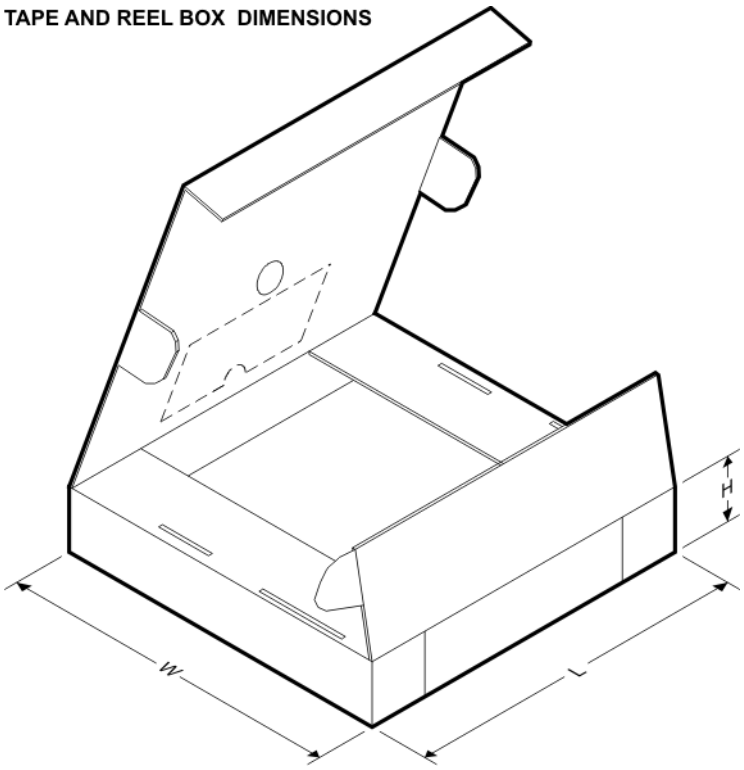
TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL061ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL061CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL061CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL061CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL061IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL061IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062ACPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL062BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL062CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL062CPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL062IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL062IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL064ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL064BCDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL064CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL064CNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL064CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL064IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL064IDRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL064INSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



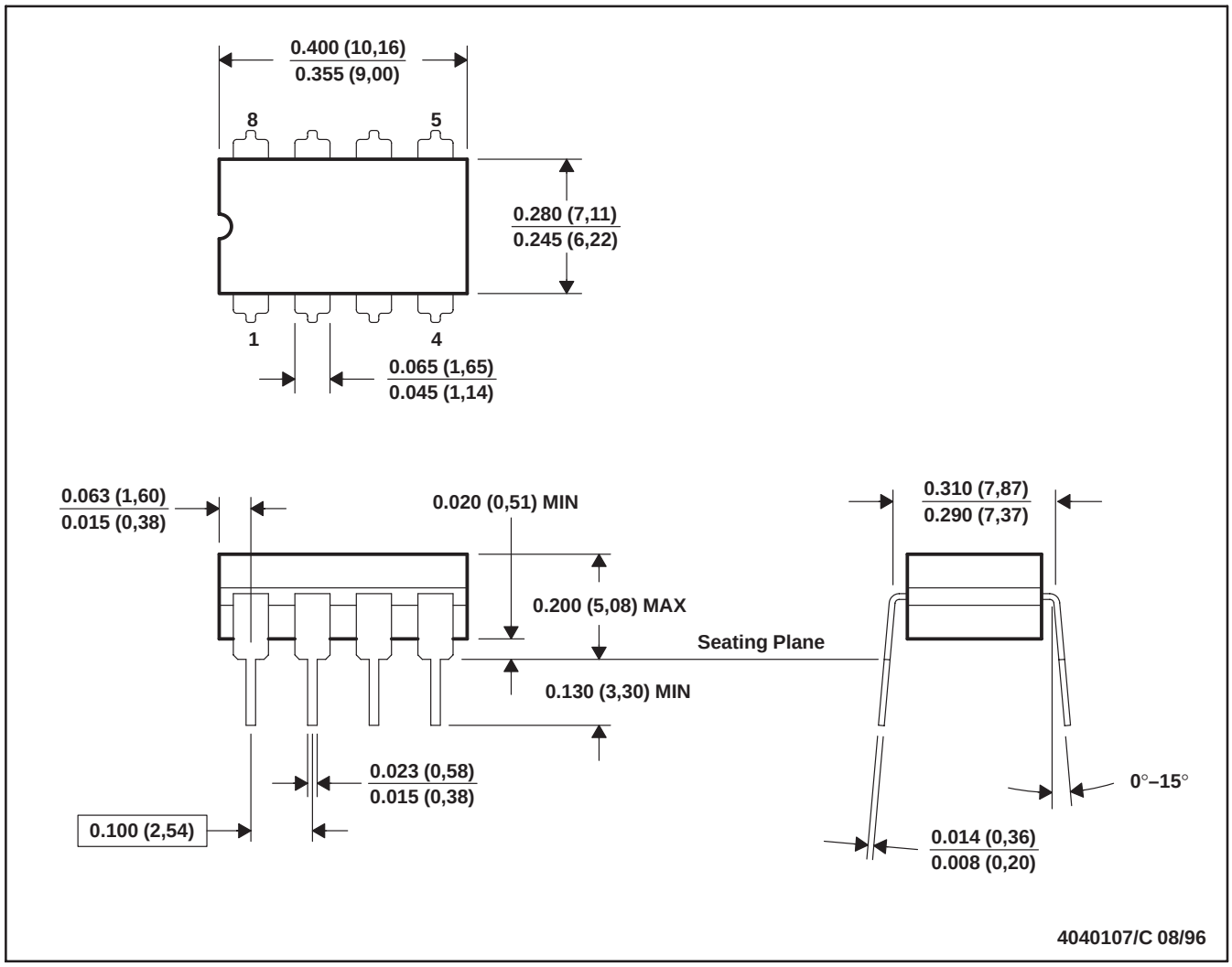
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL061ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL061CDR	SOIC	D	8	2500	367.0	367.0	35.0
TL061CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL061CPSR	SO	PS	8	2000	367.0	367.0	38.0
TL061IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL061IDR	SOIC	D	8	2500	367.0	367.0	35.0
TL062ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL062ACPSR	SO	PS	8	2000	367.0	367.0	38.0
TL062BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL062CDR	SOIC	D	8	2500	340.5	338.1	20.6

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL062CDR	SOIC	D	8	2500	367.0	367.0	35.0
TL062CPSR	SO	PS	8	2000	367.0	367.0	38.0
TL062CPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TL062CPWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
TL062IDR	SOIC	D	8	2500	367.0	367.0	35.0
TL062IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL062IPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TL064ACDR	SOIC	D	14	2500	367.0	367.0	38.0
TL064BCDR	SOIC	D	14	2500	367.0	367.0	38.0
TL064CDR	SOIC	D	14	2500	367.0	367.0	38.0
TL064CNSR	SO	NS	14	2000	367.0	367.0	38.0
TL064CPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TL064IDR	SOIC	D	14	2500	367.0	367.0	38.0
TL064IDRG4	SOIC	D	14	2500	367.0	367.0	38.0
TL064INSR	SO	NS	14	2000	367.0	367.0	38.0

MCER001A – JANUARY 1995 – REVISED JANUARY 1997

JG (R-GDIP-T8) **CERAMIC DUAL-IN-LINE**

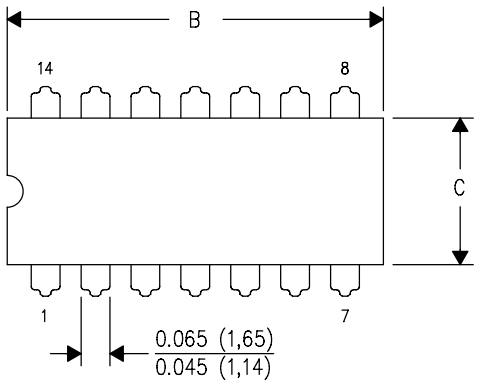


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification.
E. Falls within MIL STD 1835 GDIP1-T8

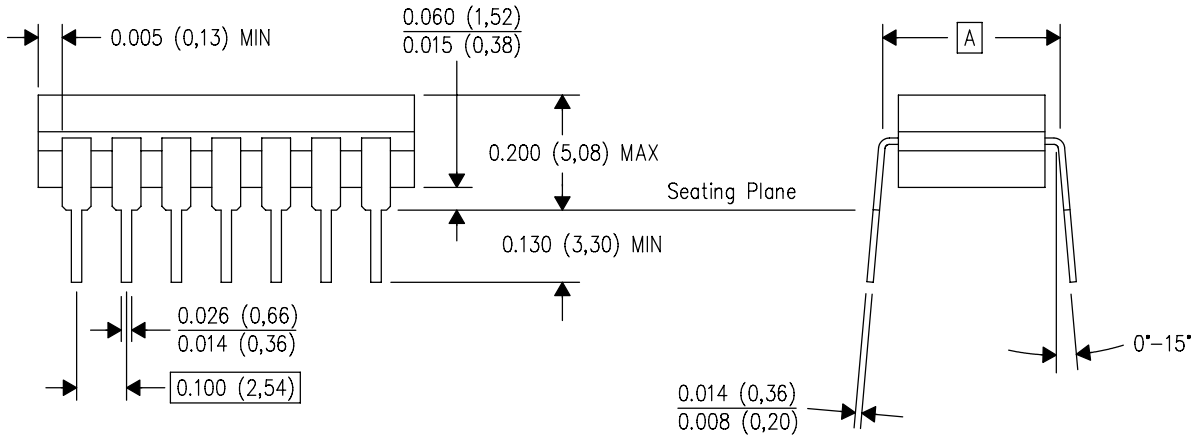
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



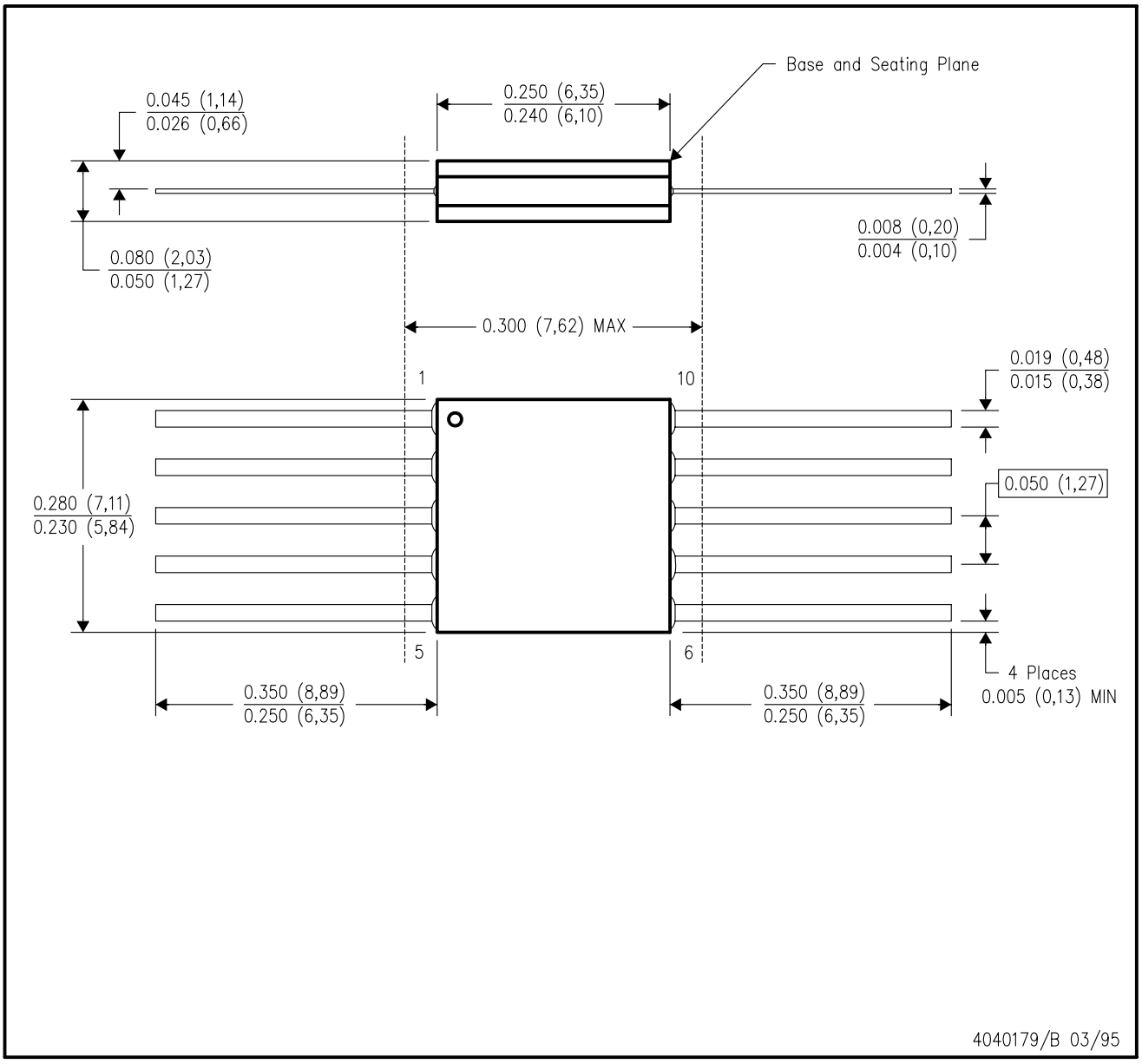
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

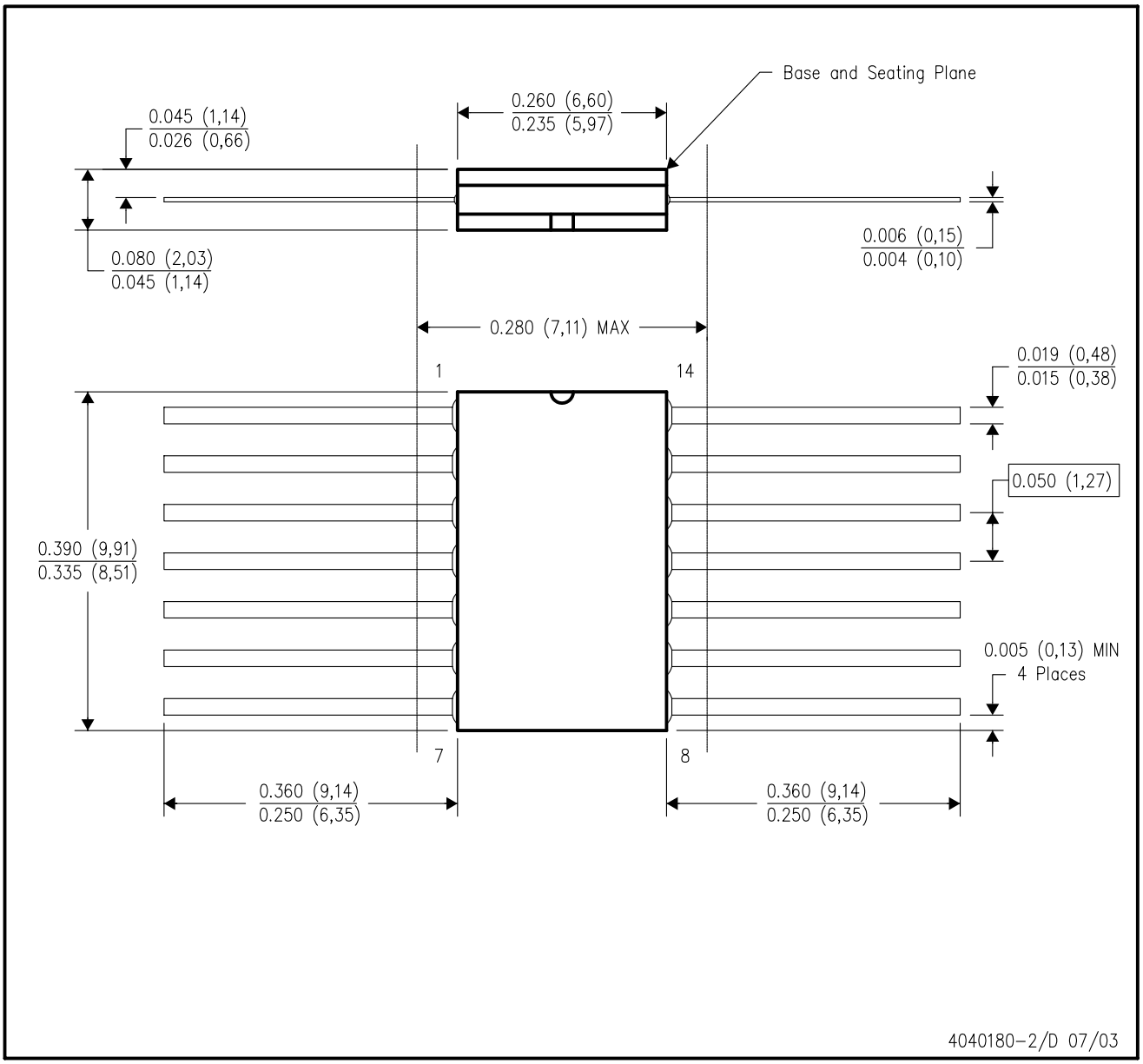
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

U (S–GDFP–F10) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F10 and JEDEC MO–092AA

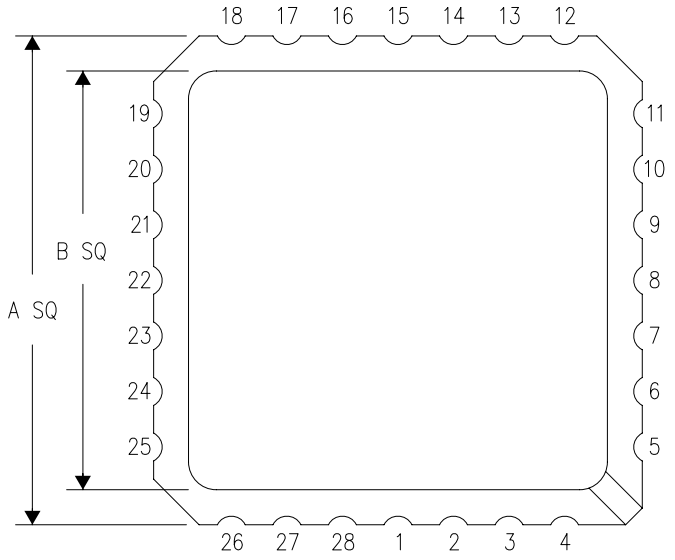
W (R–GDFP–F14) CERAMIC DUAL FLATPACK



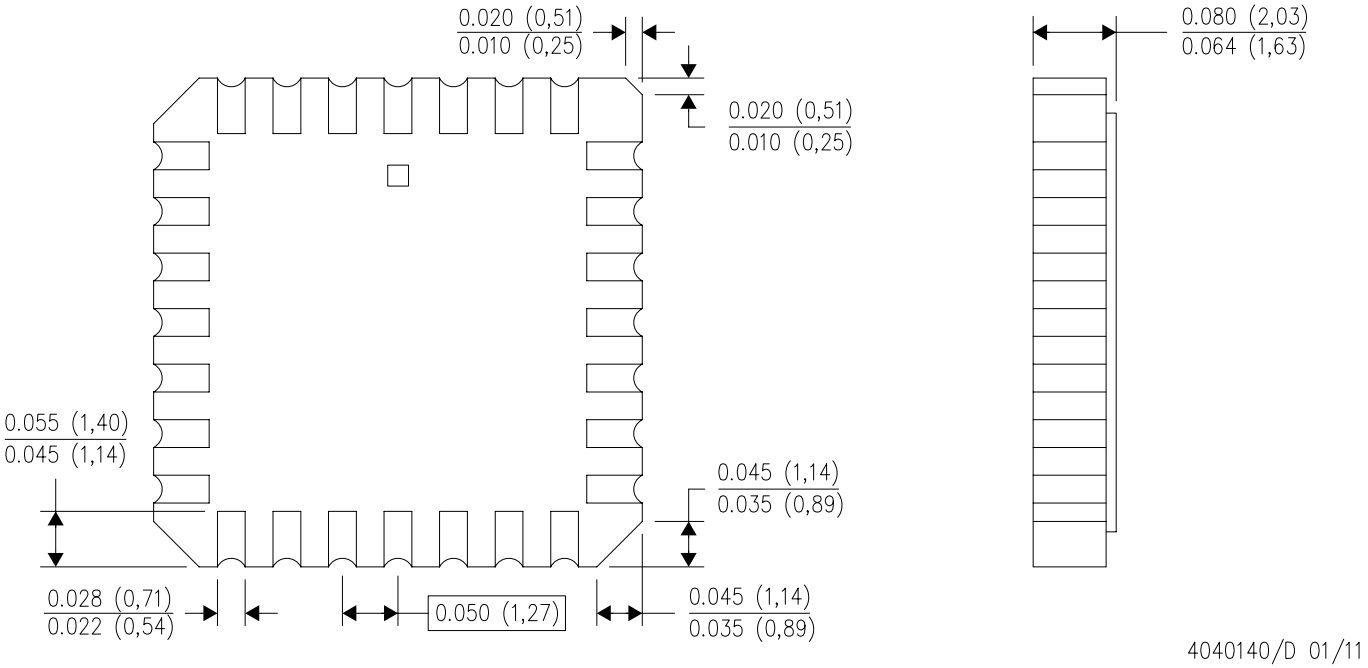
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



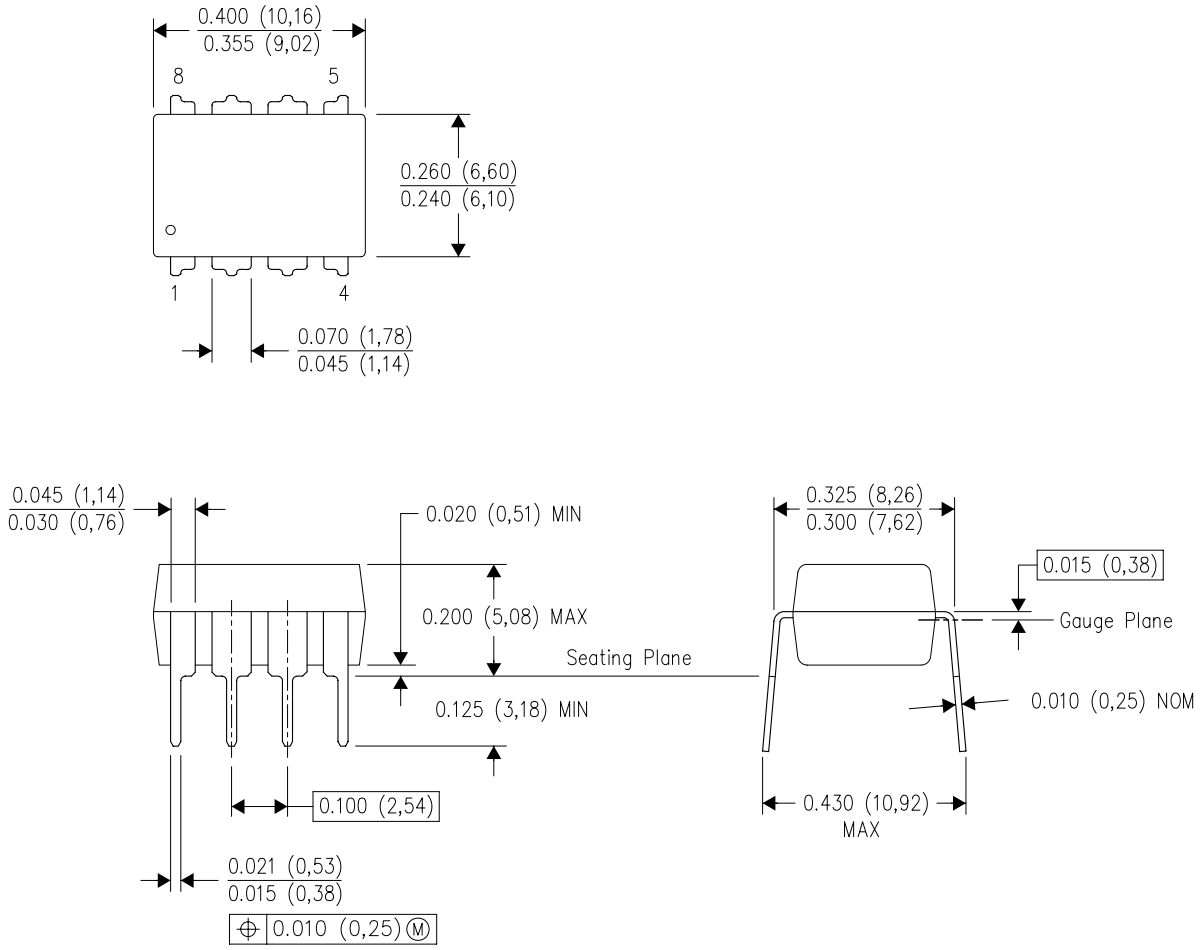
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE

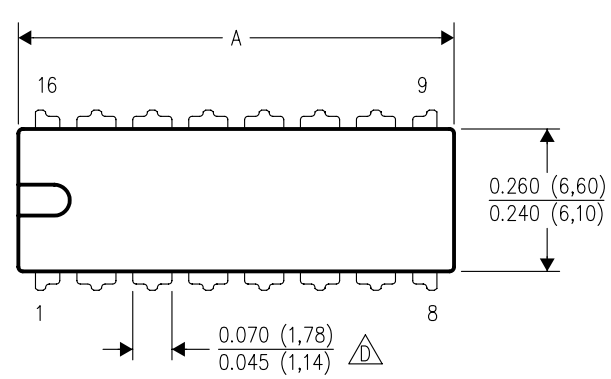


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

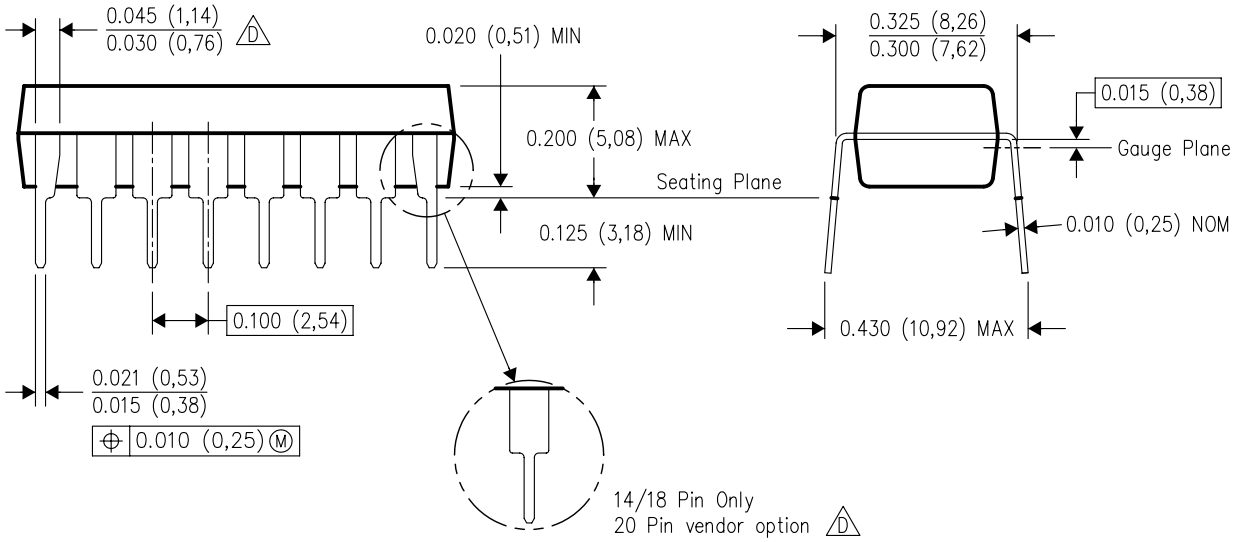
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



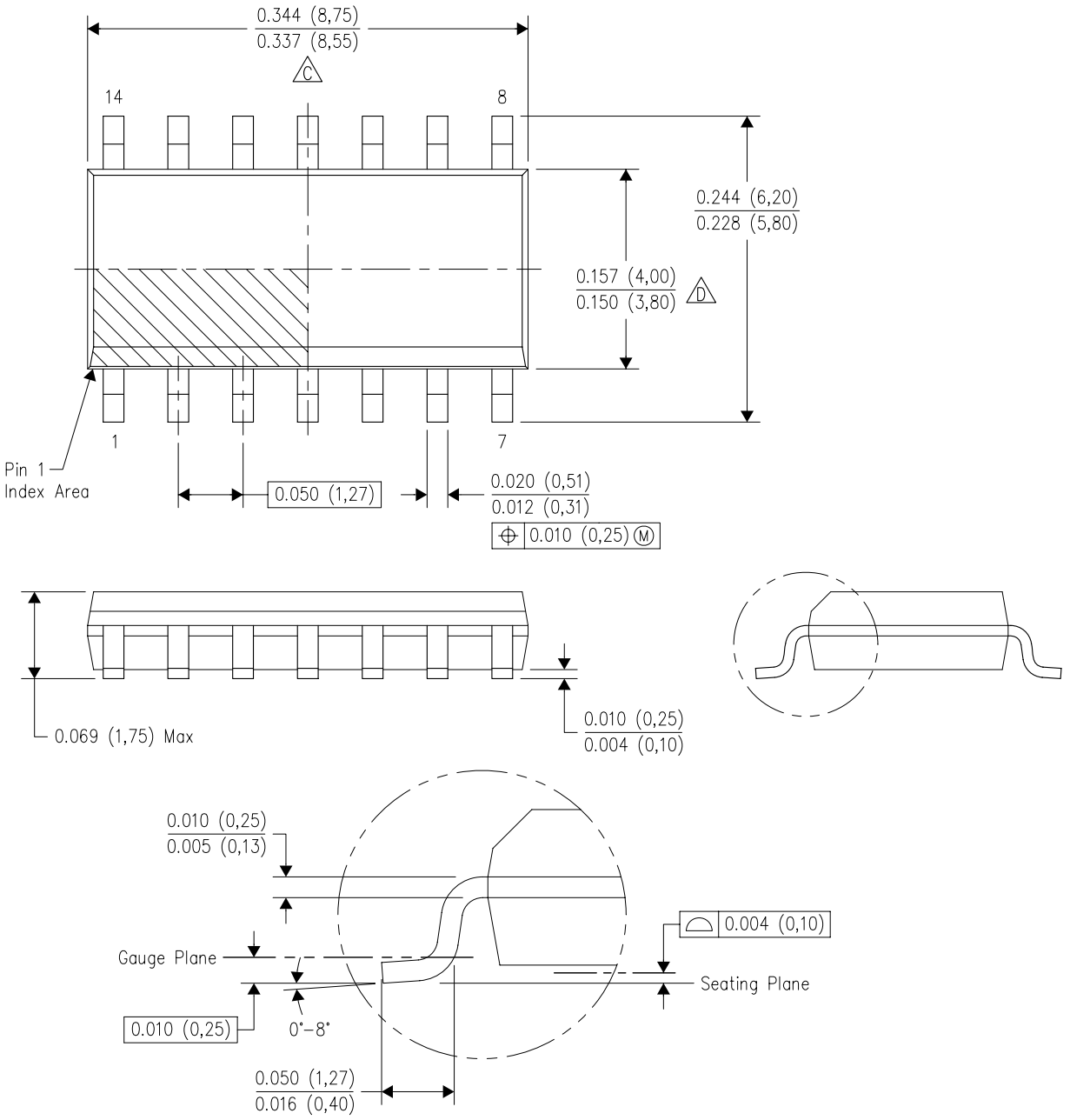
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

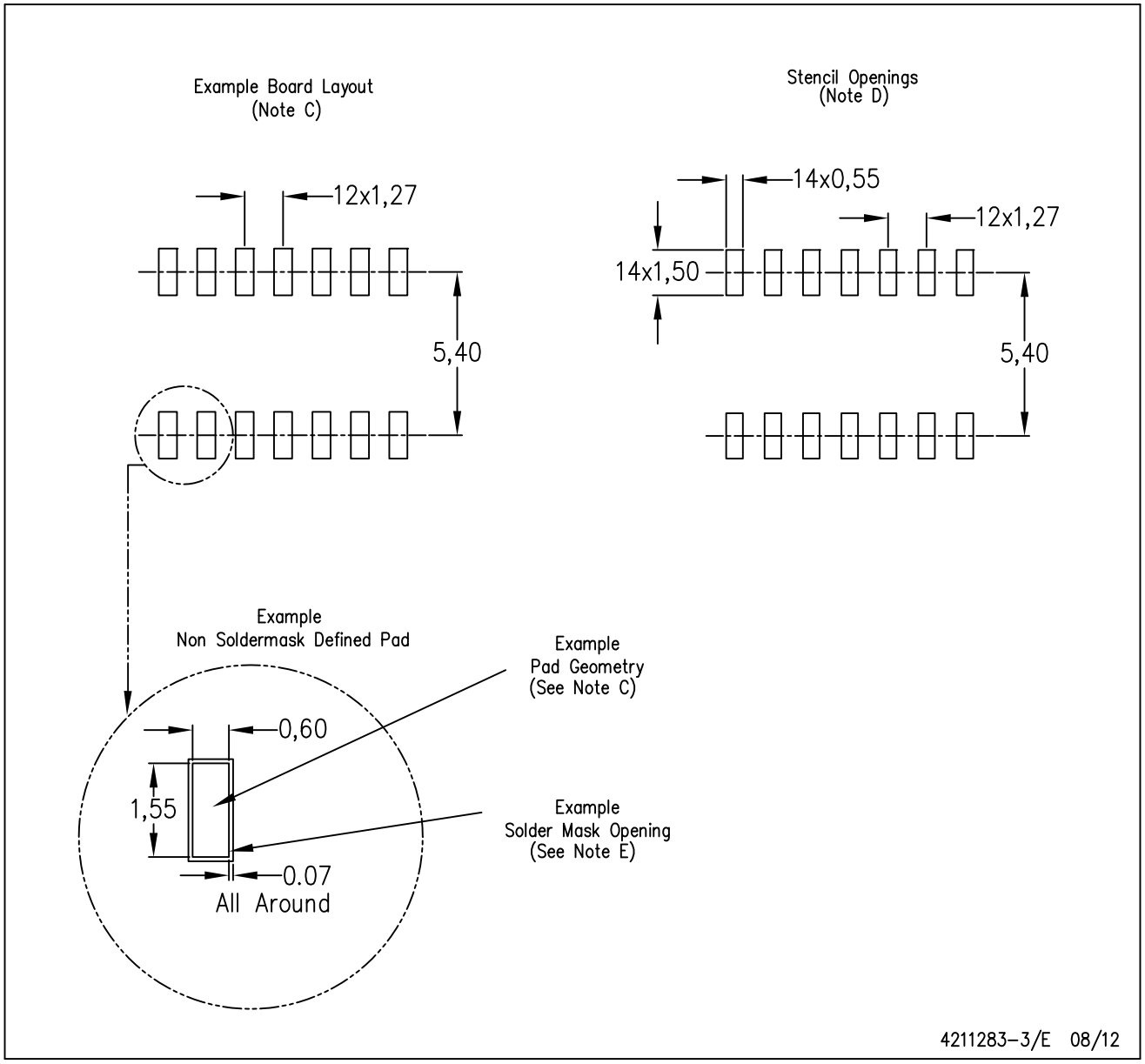
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

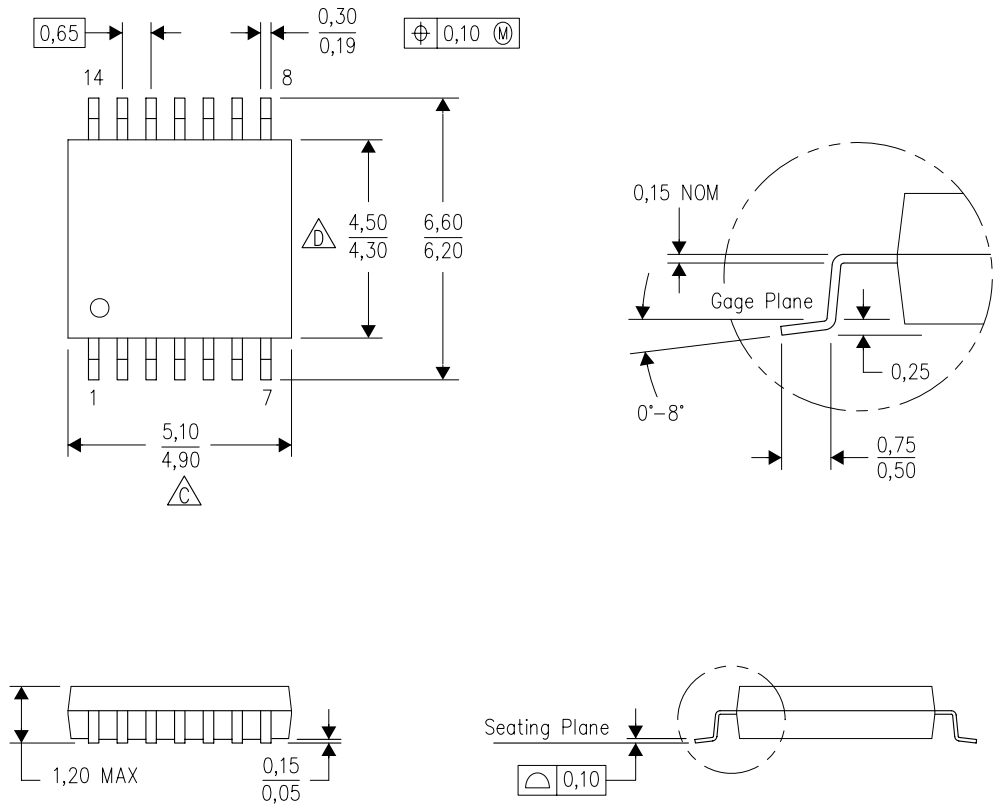
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

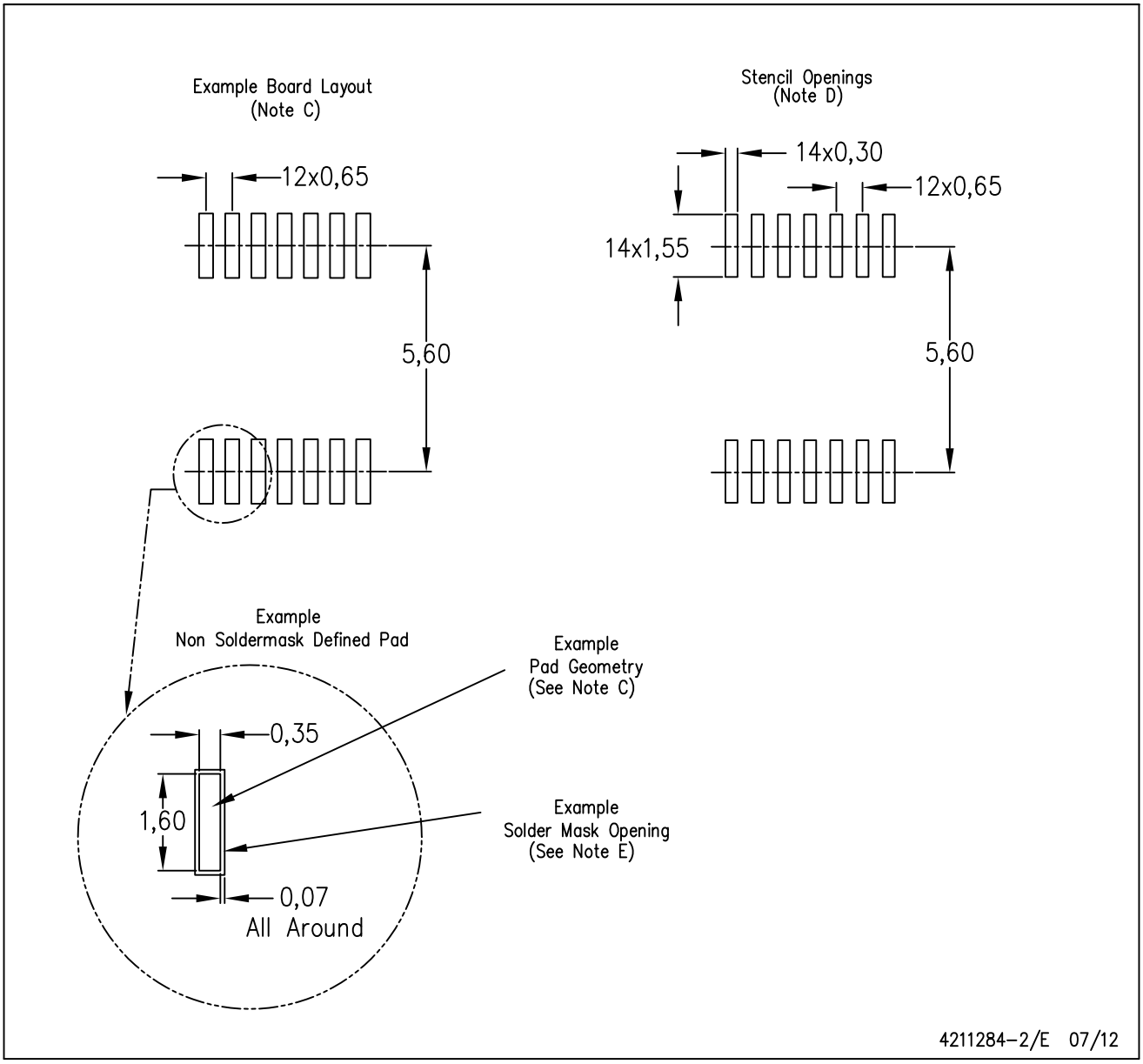
PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040064–3/G 02/11

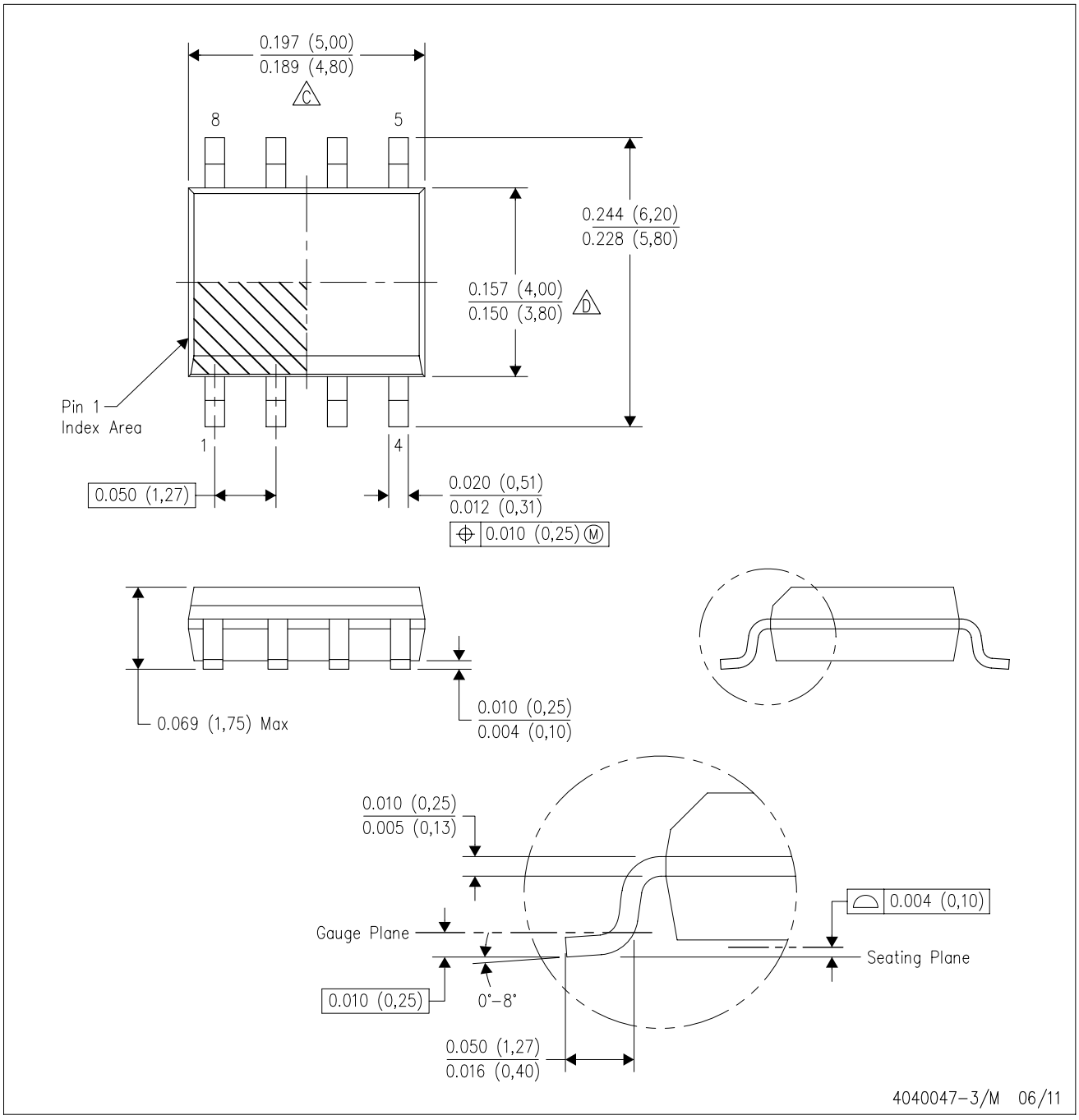
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



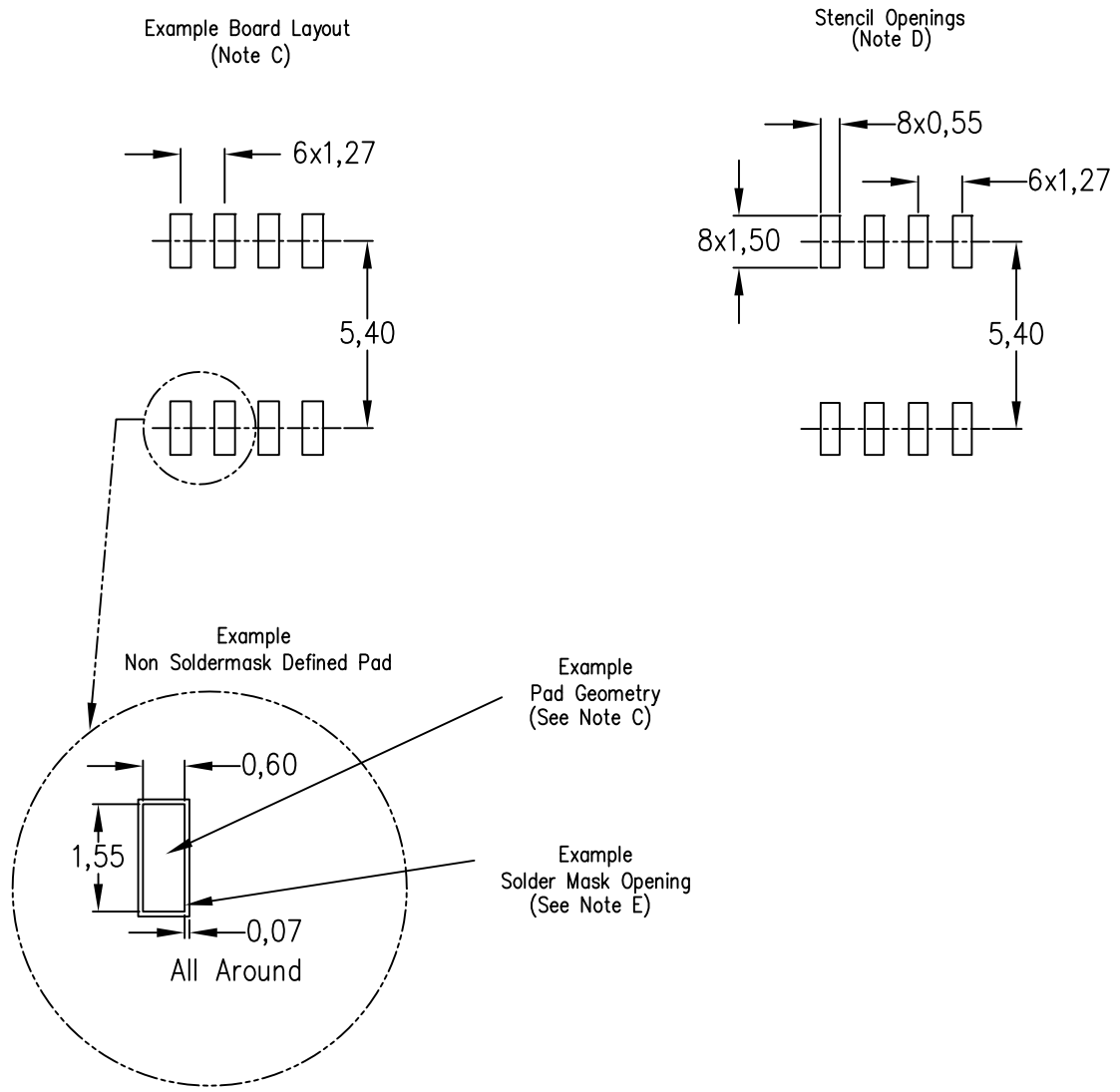
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

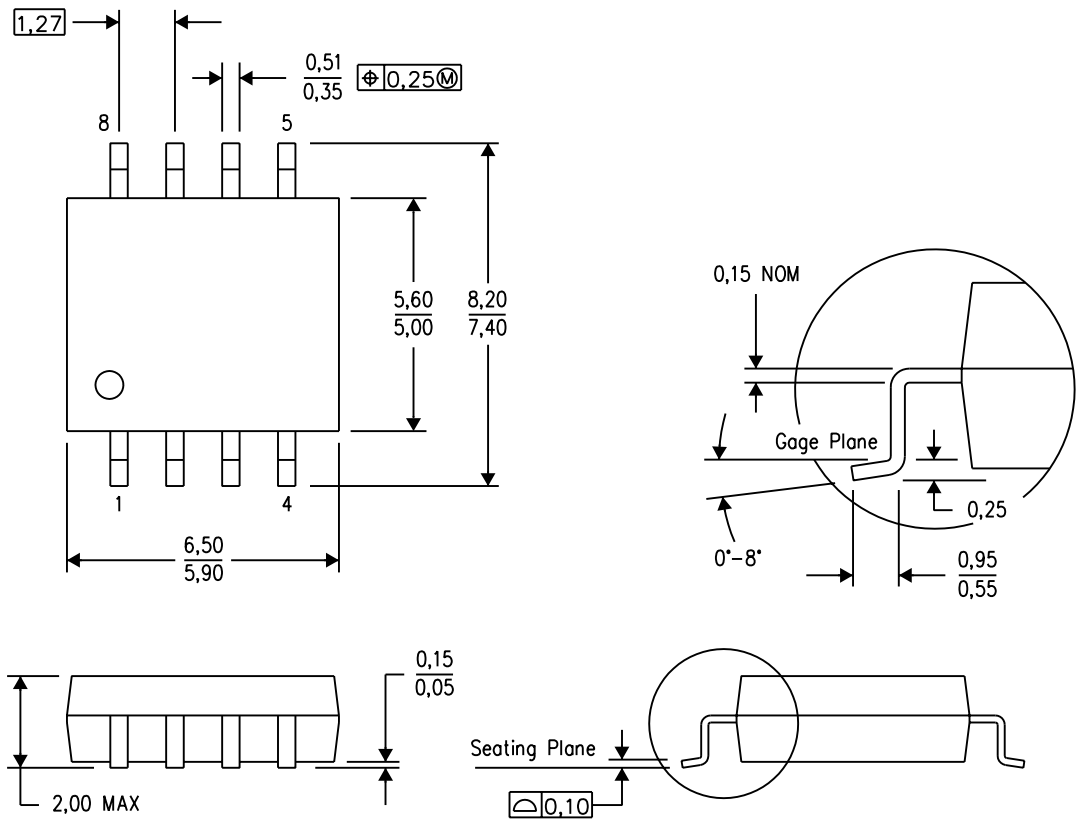
D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

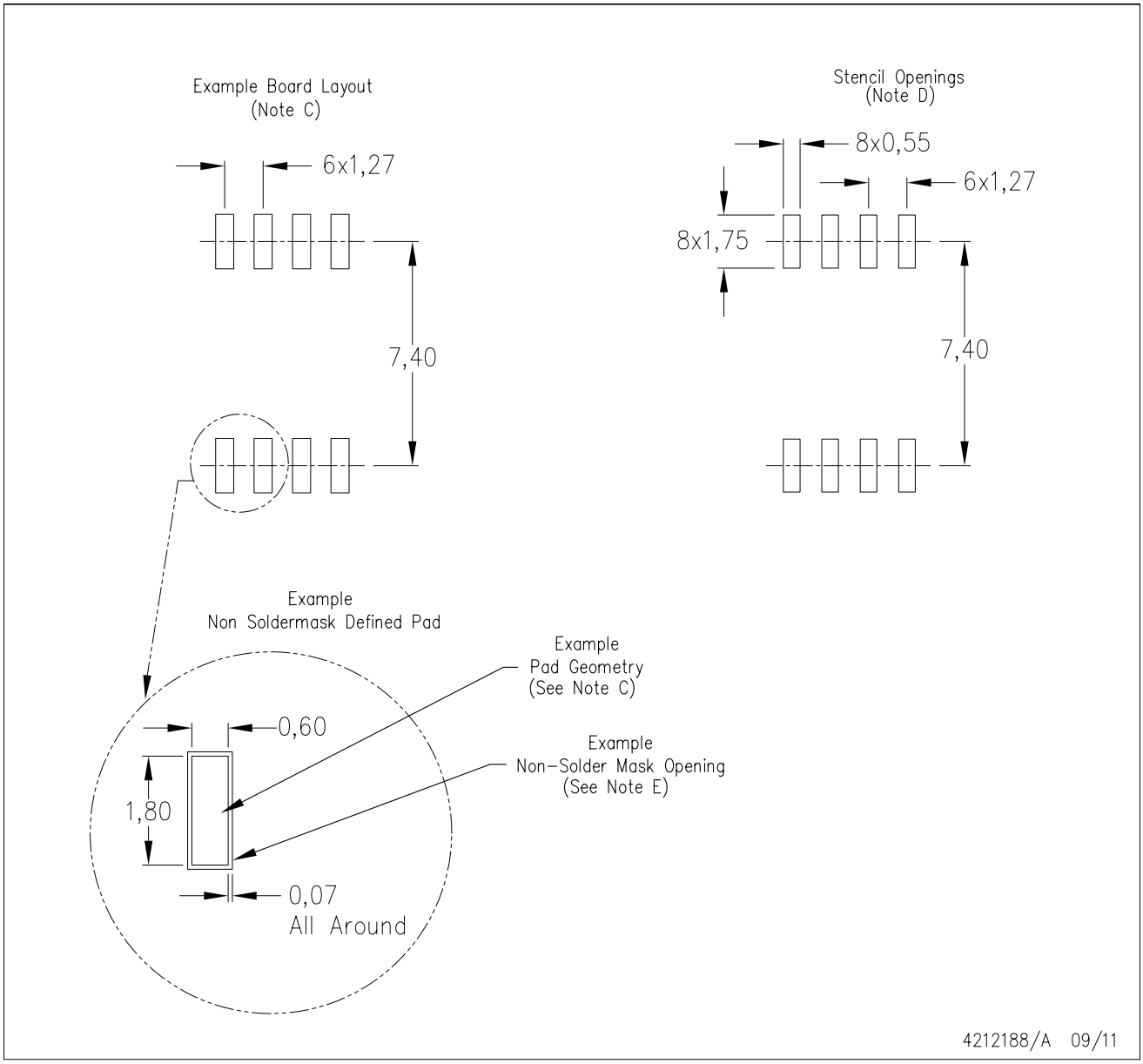
PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



4040063/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R–PDSO–G8) PLASTIC SMALL OUTLINE

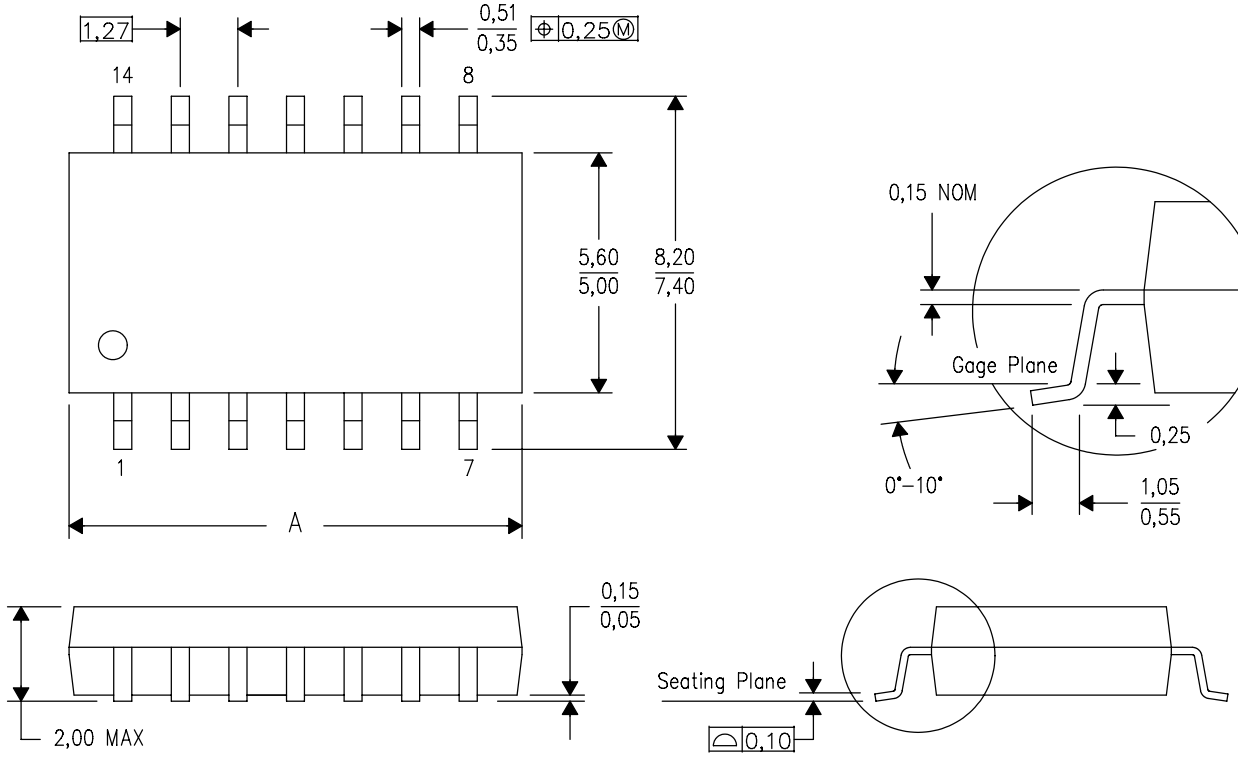


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

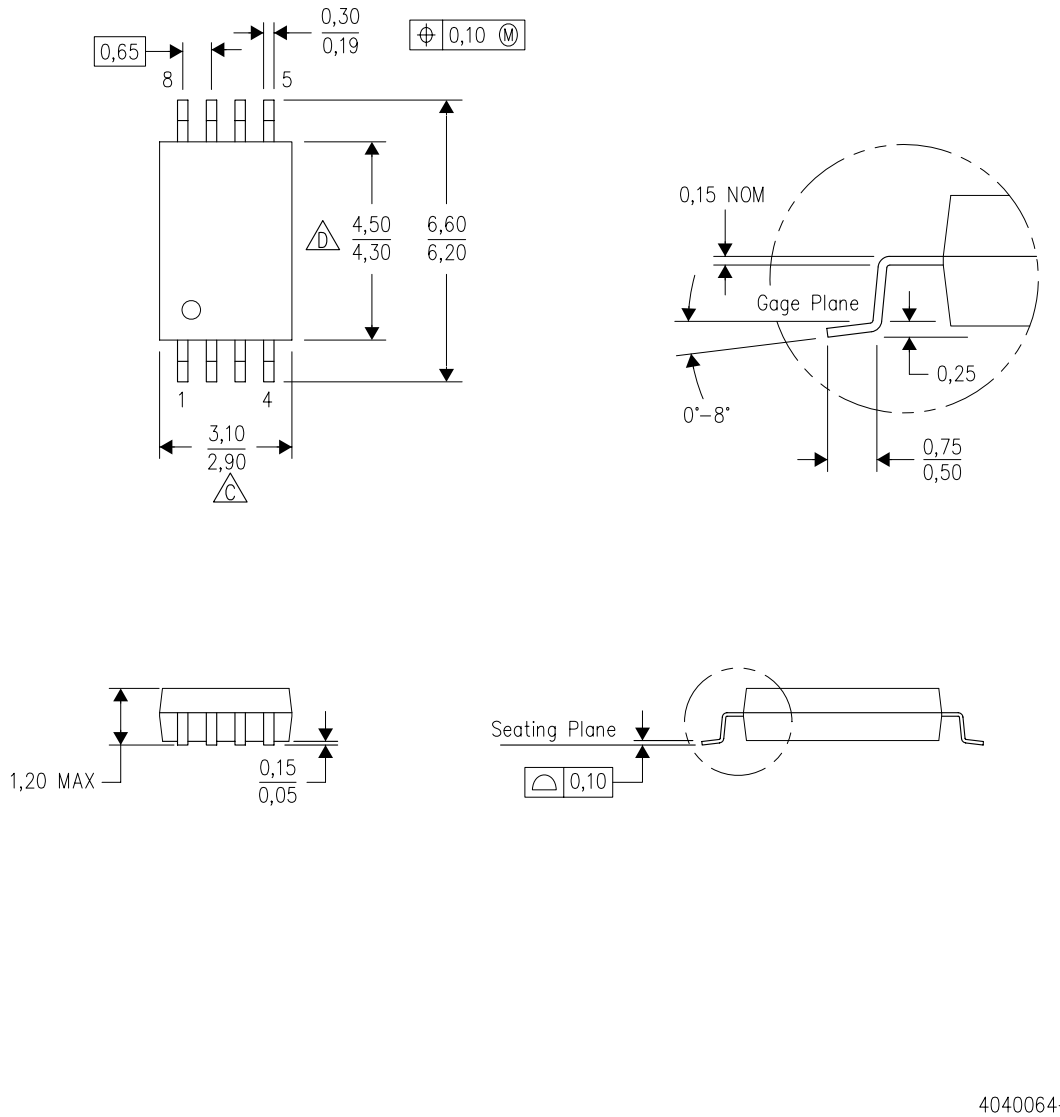


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R–PDSO–G8) PLASTIC SMALL OUTLINE



4040064–2/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

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